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(12) **United States Design Patent**
Reiherzer et al.

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(54) **LED PACKAGE WITH ENCAPSULANT**
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(**) Term: **14 Years**

(21) Appl. No.: **29/462,353**

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(51) **LOC (10) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/180**

(58) **Field of Classification Search**
USPC D13/180; D26/1; 257/79, 80, 81, 88,
257/89, 95, 98, 99, 100, E33.058; 313/483,
313/498, 500; 362/555, 800
See application file for complete search history.

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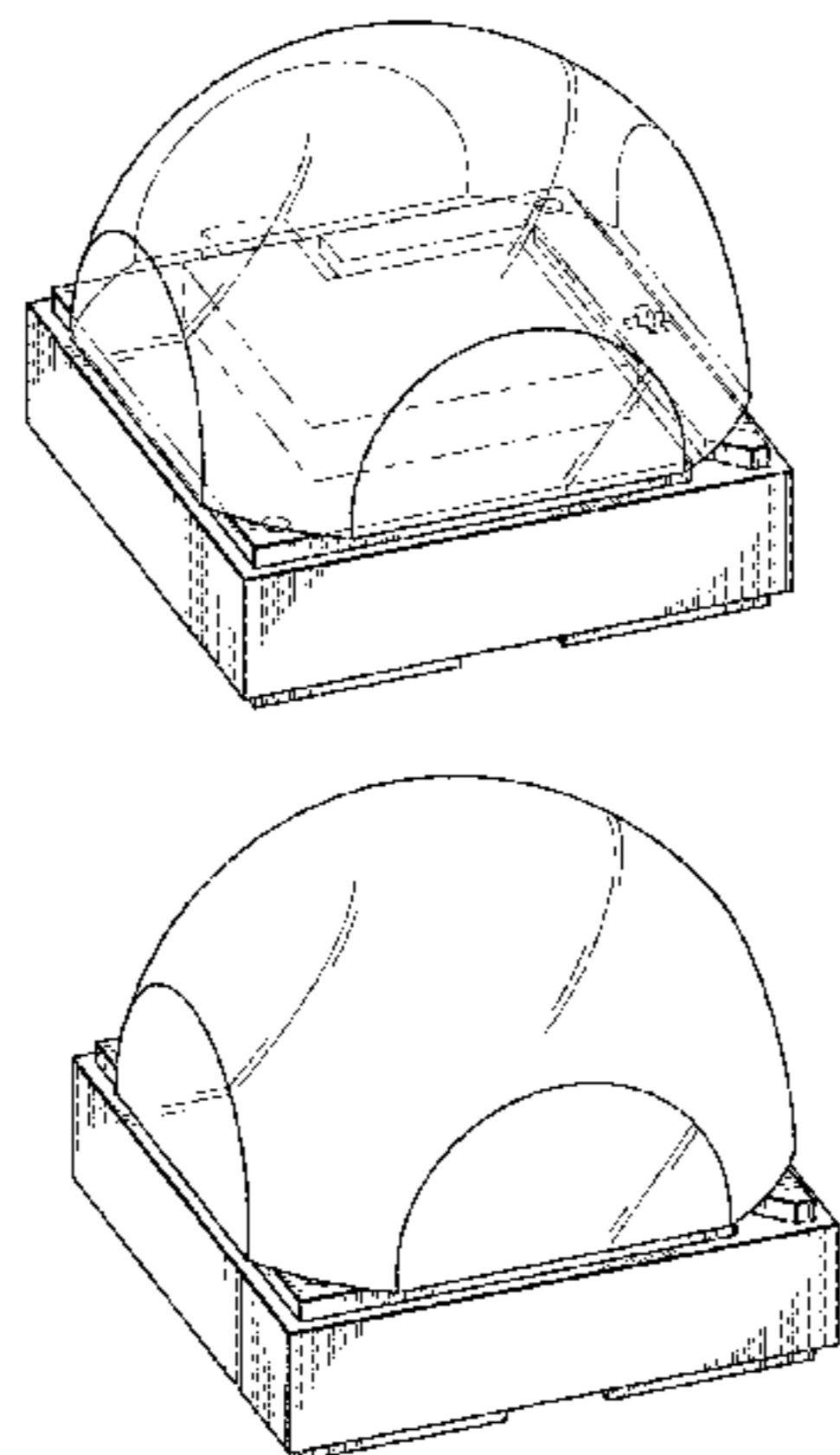
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Primary Examiner — Selina Sikder
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(57) **CLAIM**
 The ornamental design for LED package with encapsulant, as shown and described herein.

DESCRIPTION

FIG. 1 is a top perspective view of an LED package according to one embodiment of the present invention.
 FIG. 2 is a top view of the LED package shown in FIG. 1.
 FIG. 3 is a bottom view of the LED package shown in FIG. 1.
 FIG. 4 is a front elevation view of the LED package shown in FIG. 1.
 FIG. 5 is a back elevation view of the LED package as shown in FIG. 1.
 FIG. 6 is a right elevation view of the LED package shown in FIG. 1.
 FIG. 7 is a left elevation view of the LED package shown in FIG. 1.
 FIG. 8 is a top perspective view of an LED package according to one embodiment of the present invention.
 FIG. 9 is a top view of the LED package with encapsulant shown in FIG. 8.
 FIG. 10 is a bottom view of the LED package shown in FIG. 8.
 FIG. 11 is a front elevation view of the LED package shown in FIG. 8.

FIG. 12 is a back elevation view of the LED package as shown in FIG. 8.
 FIG. 13 is a right elevation view of the LED package shown in FIG. 8.
 FIG. 14 is a left elevation view of the LED package shown in FIG. 8.
 FIG. 15 is a top perspective view of an LED package according to one embodiment of the present invention.
 FIG. 16 is a top view of the LED package shown in FIG. 15.
 FIG. 17 is a bottom view of the LED package shown in FIG. 15.
 FIG. 18 is a front elevation view of the LED package shown in FIG. 15.
 FIG. 19 is a back elevation view of the LED package as shown in FIG. 15.
 FIG. 20 is a right elevation view of the LED package shown in FIG. 15.
 FIG. 21 is a left elevation view of the LED package shown in FIG. 15.
 FIG. 22 is a top perspective view of an LED package according to one embodiment of the present invention.
 FIG. 23 is a top view of the LED package shown in FIG. 22.
 FIG. 24 is a bottom view of the LED package shown in FIG. 22.
 FIG. 25 is a front elevation view of the LED package shown in FIG. 22.
 FIG. 26 is a back elevation view of the LED package as shown in FIG. 22.
 FIG. 27 is a right elevation view of the LED package shown in FIG. 22.
 FIG. 28 is a left elevation view of the LED package shown in FIG. 22.
 FIG. 29 is a top perspective view of an LED package according to one embodiment of the present invention.
 FIG. 30 is a top view of the LED package shown in FIG. 29.
 FIG. 31 is a bottom view of the LED package shown in FIG. 29.
 FIG. 32 is a front elevation view of the LED package shown in FIG. 29.
 FIG. 33 is a back elevation view of the LED package as shown in FIG. 29.
 FIG. 34 is a right elevation view of the LED package shown in FIG. 29.
 FIG. 35 is a left elevation view of the LED package shown in FIG. 29.
 FIG. 36 is a top perspective view of an LED package according to one embodiment of the present invention.
 FIG. 37 is a top view of the LED package shown in FIG. 36;
 FIG. 38 is a bottom view of the LED package shown in FIG. 36.
 FIG. 39 is a front elevation view of the LED package shown in FIG. 36.
 FIG. 40 is a back elevation view of the LED package as shown in FIG. 36.
 FIG. 41 is a right elevation view of the LED package shown in FIG. 36; and,
 FIG. 42 is a left elevation view of the LED package shown in FIG. 36.
 The broken lines shown in the above figures depict environmental subject matter only and form no part of the claimed design in those embodiments.

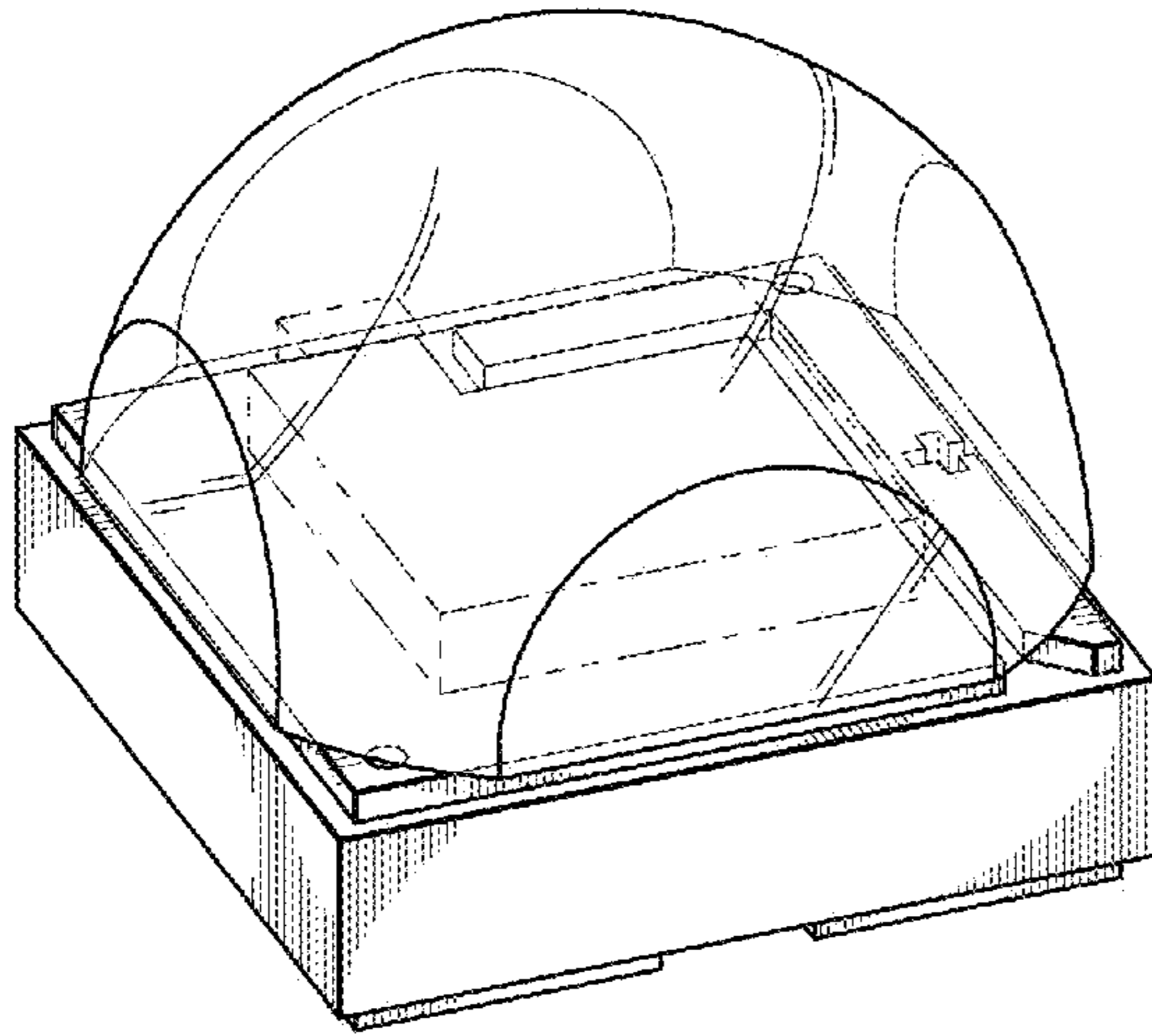


FIG. 1

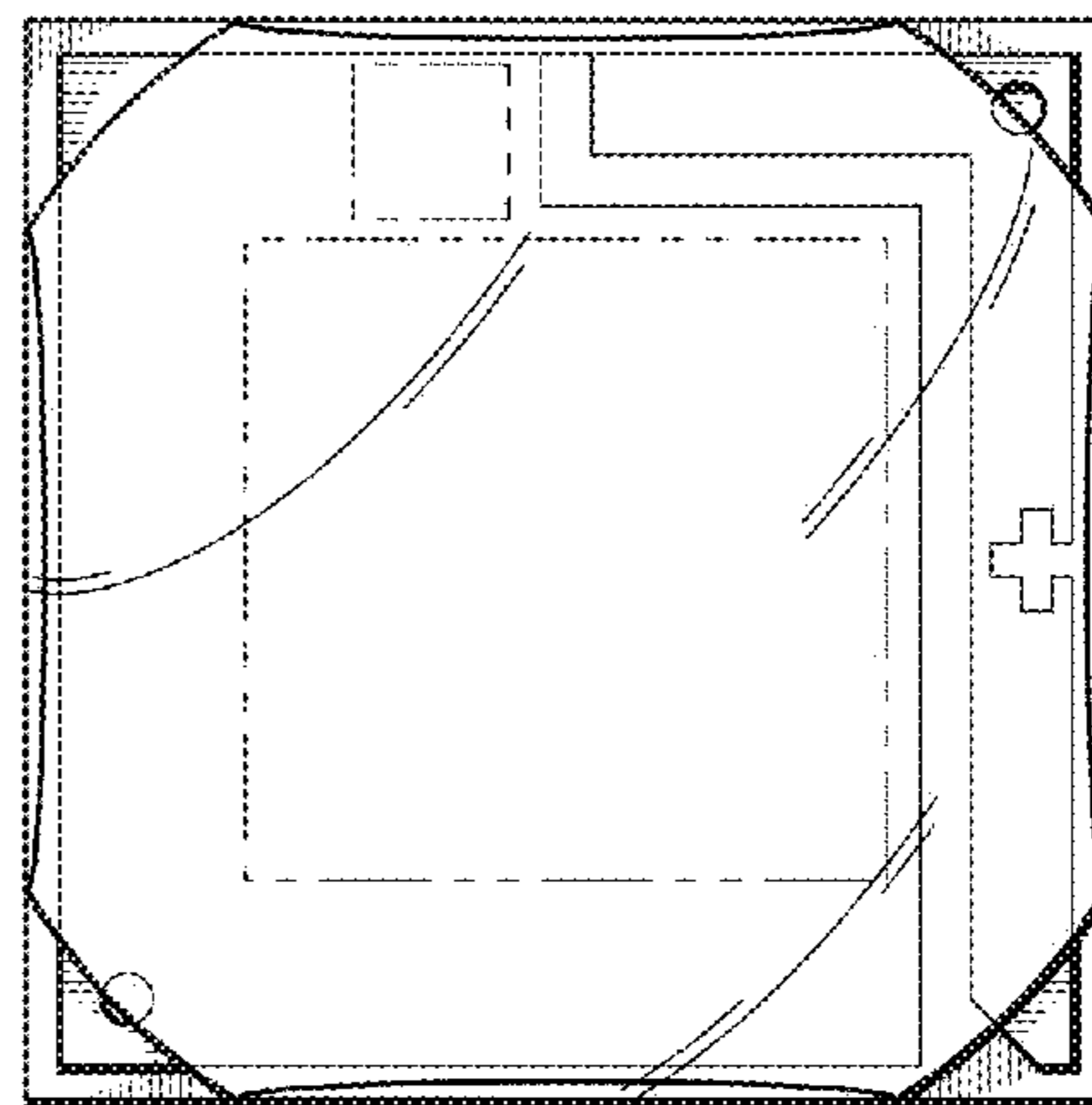


FIG. 2

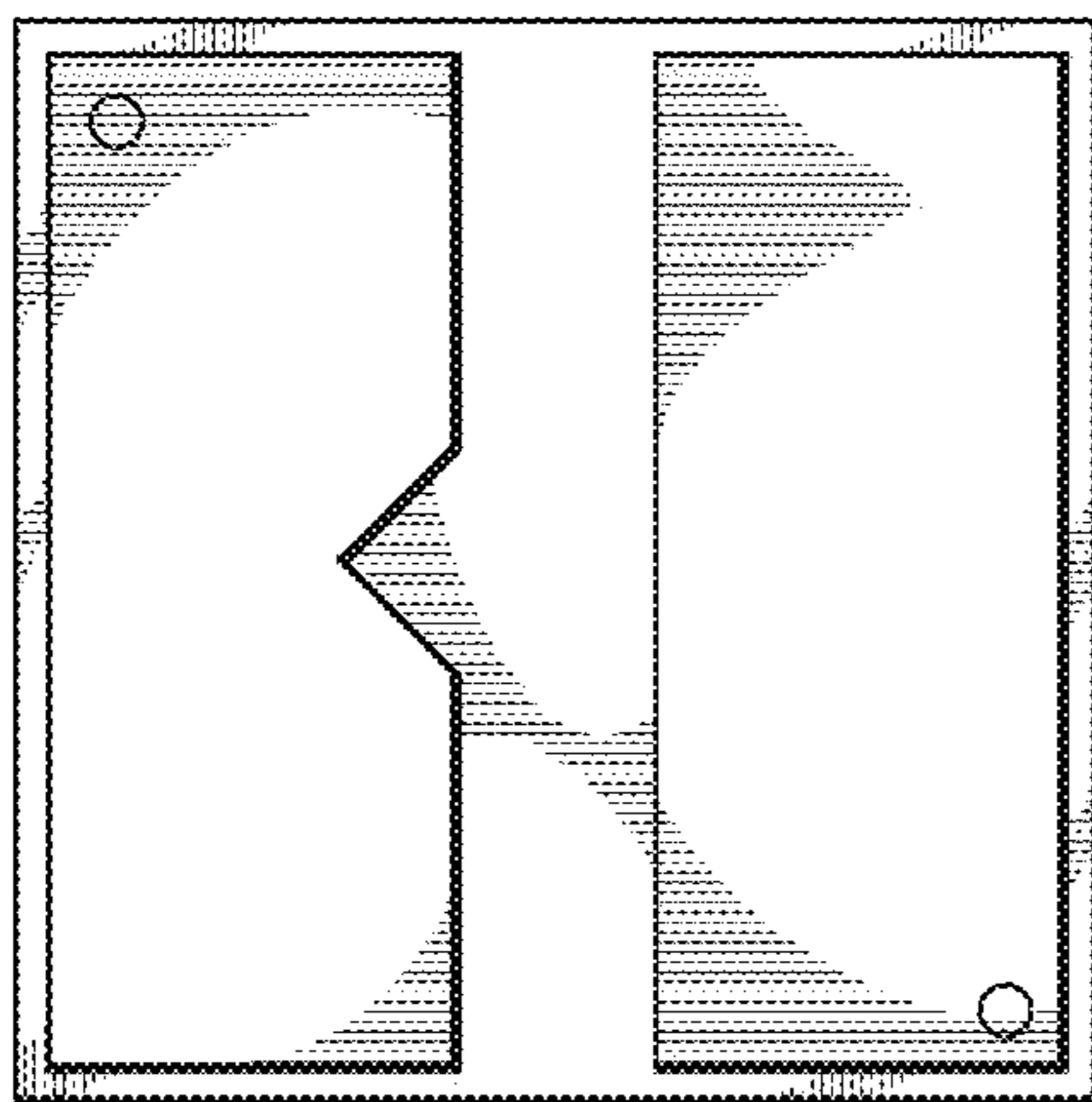


FIG. 3

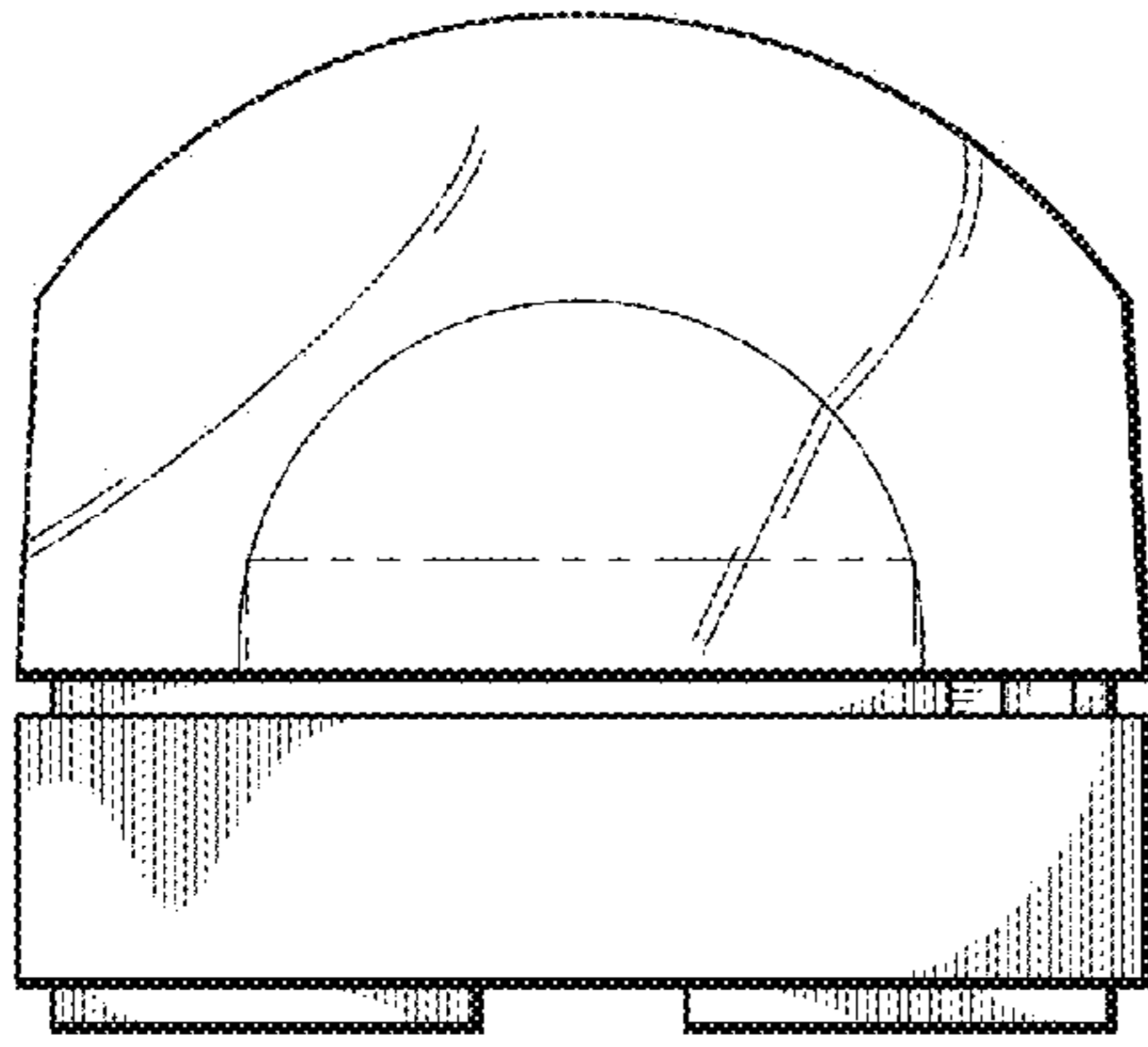


FIG. 4

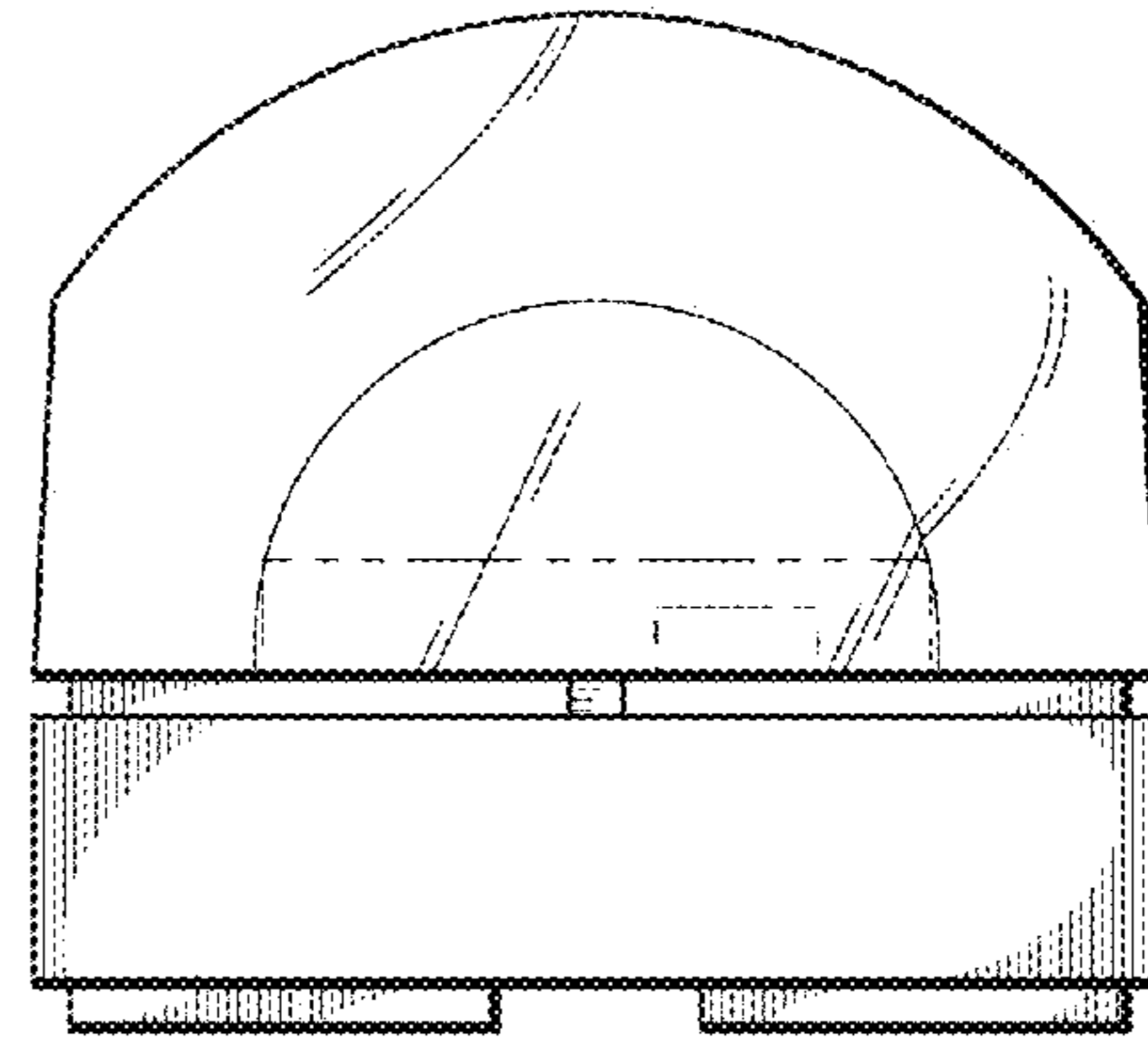


FIG. 5

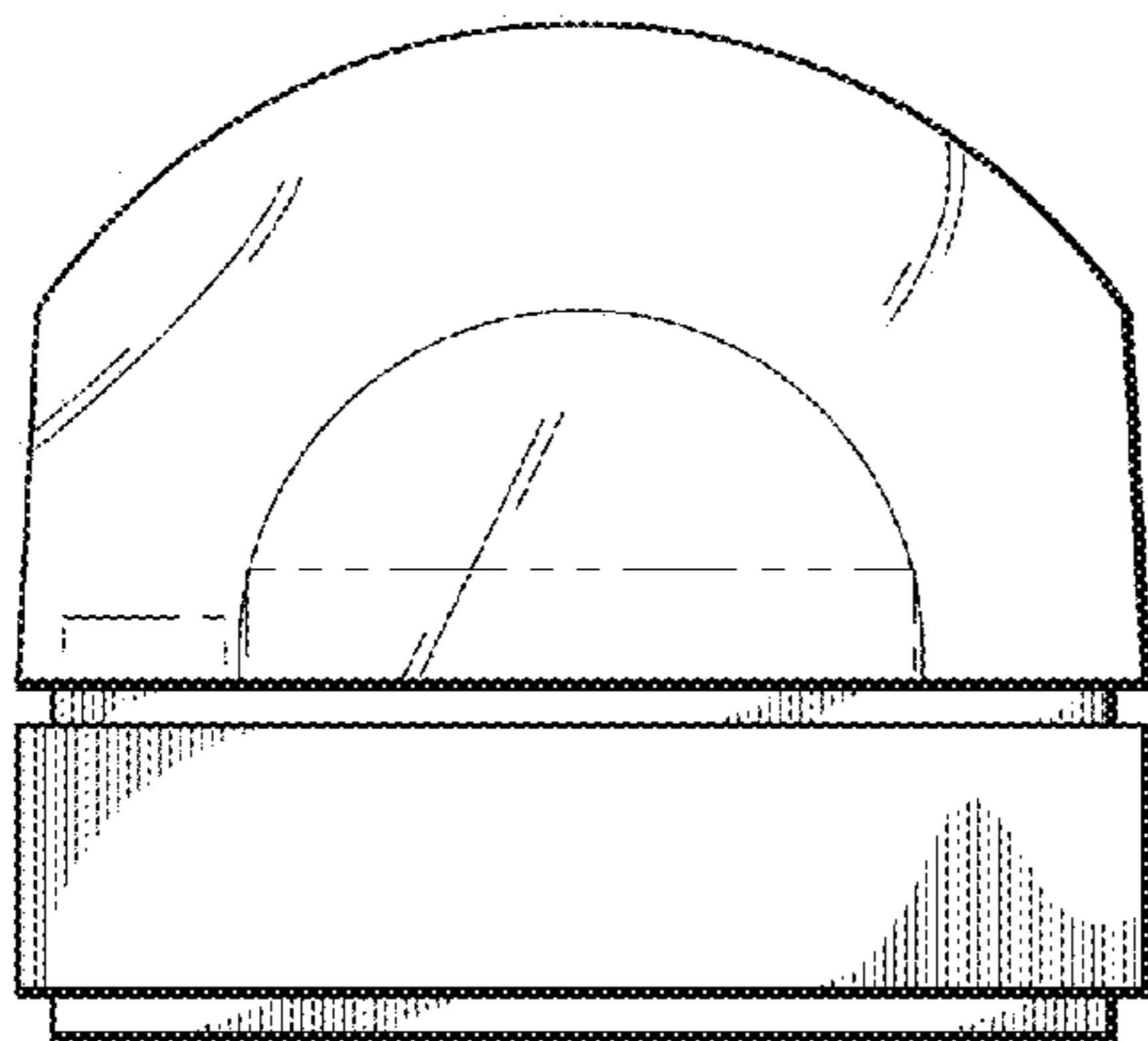


FIG. 6

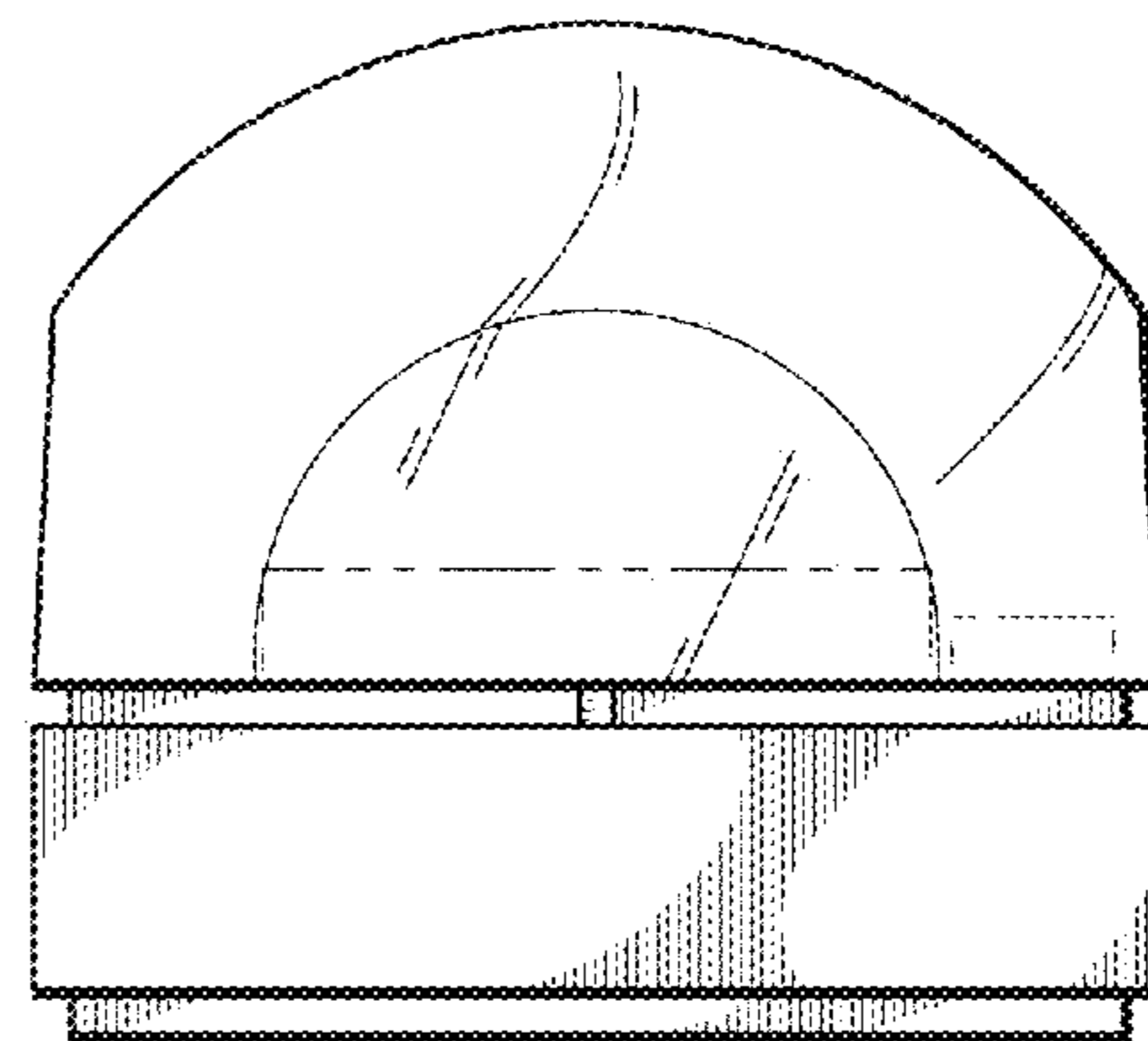


FIG. 7

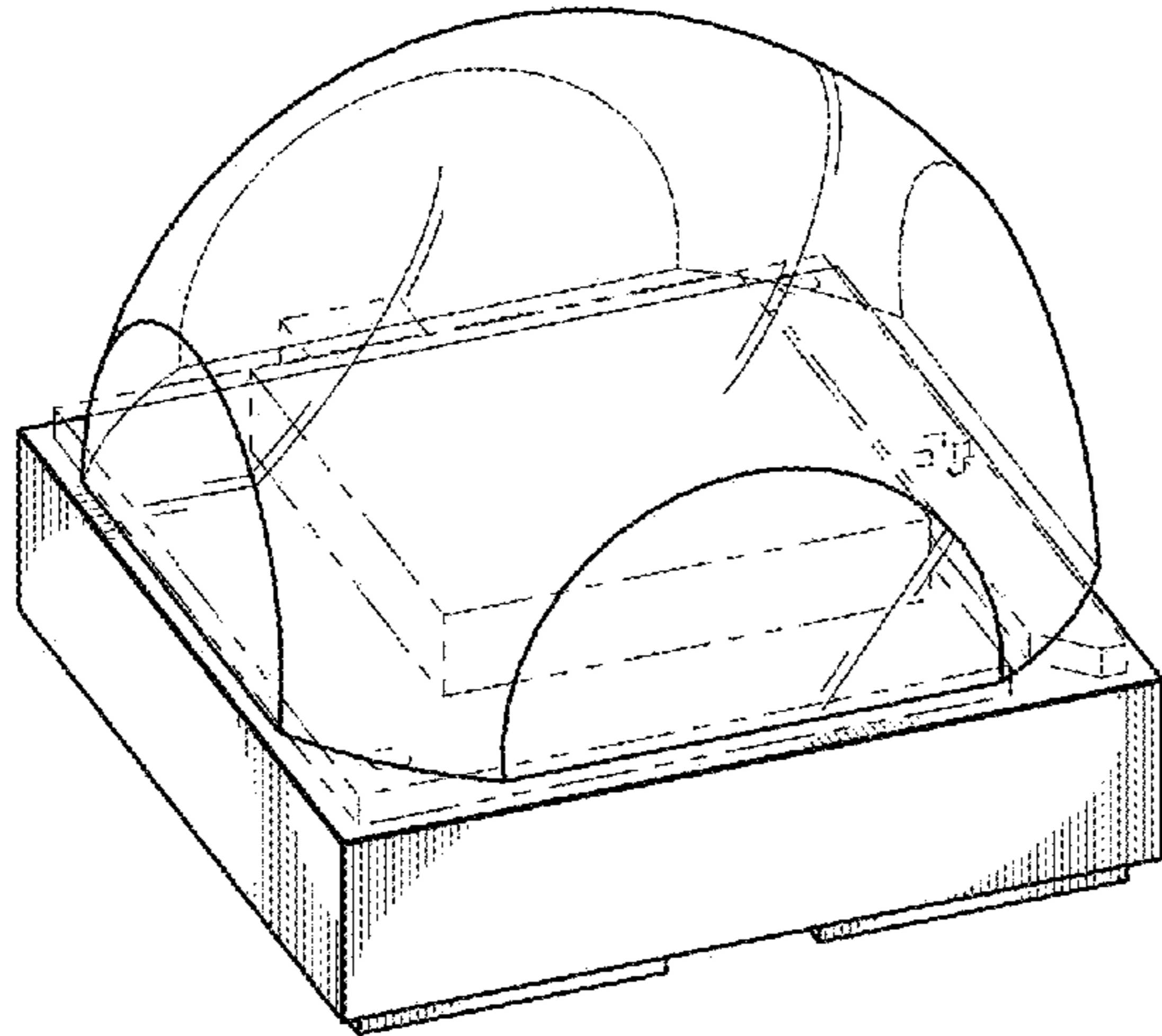


FIG. 8

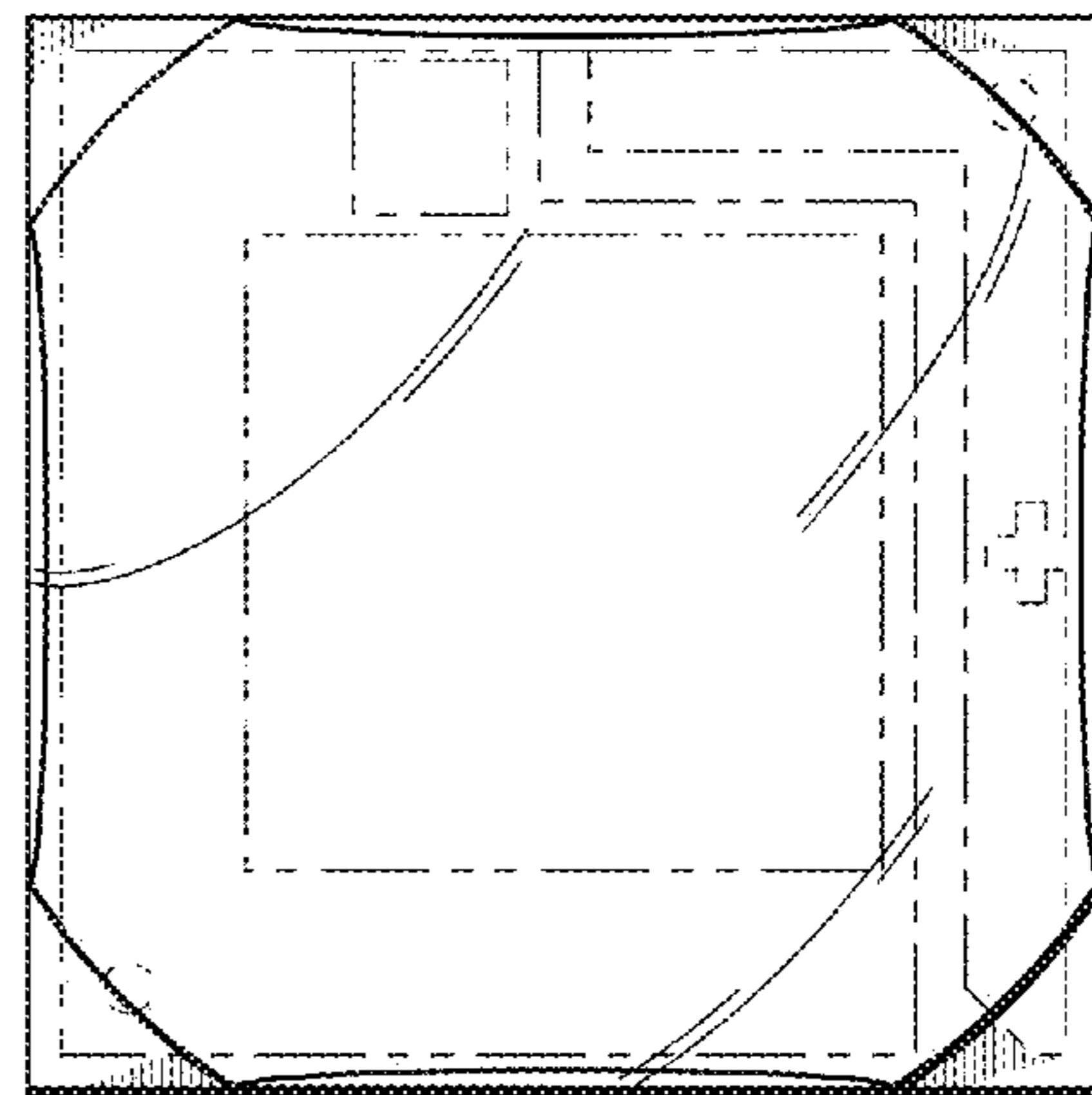


FIG. 9

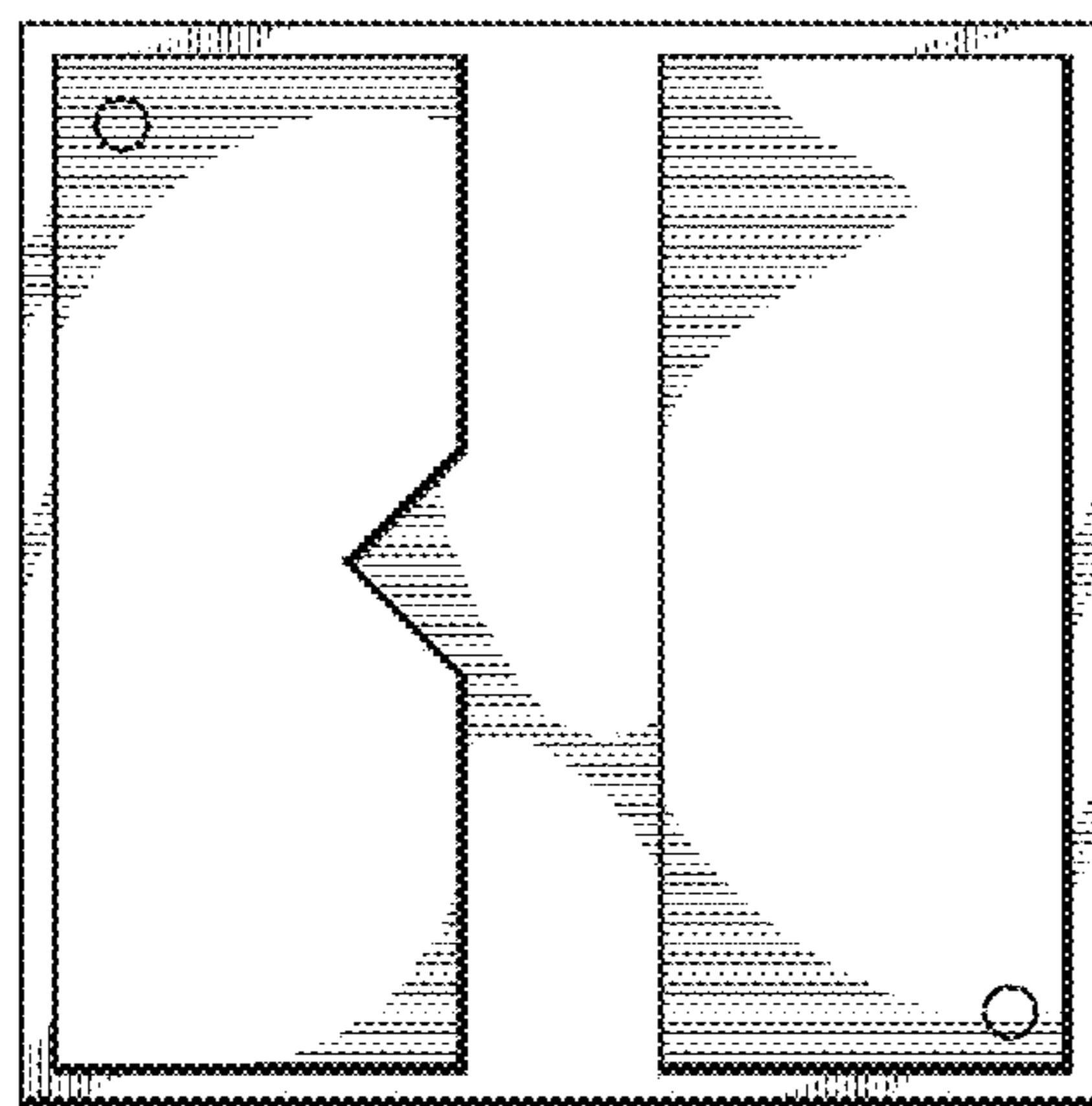


FIG. 10

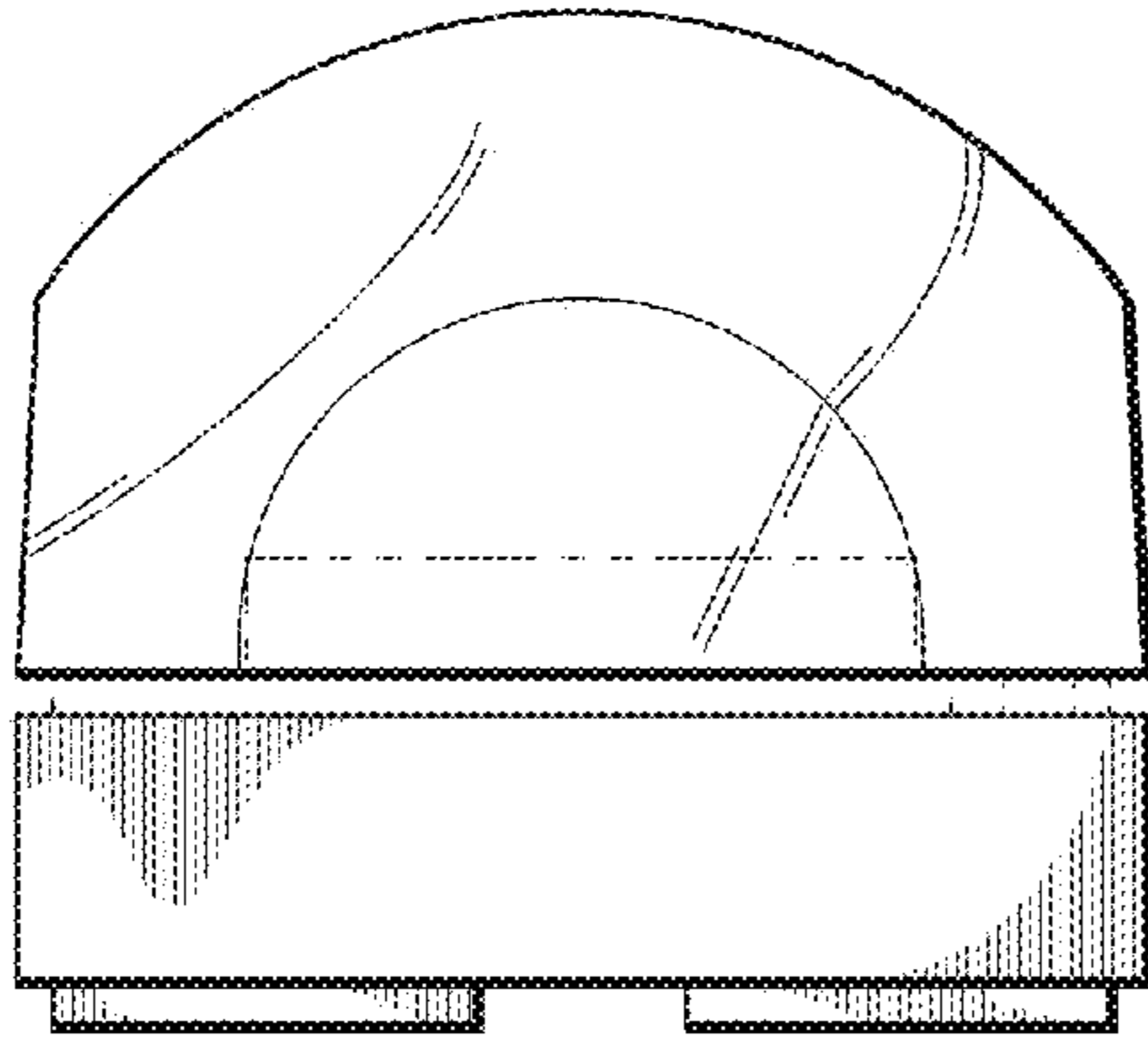


FIG. 11

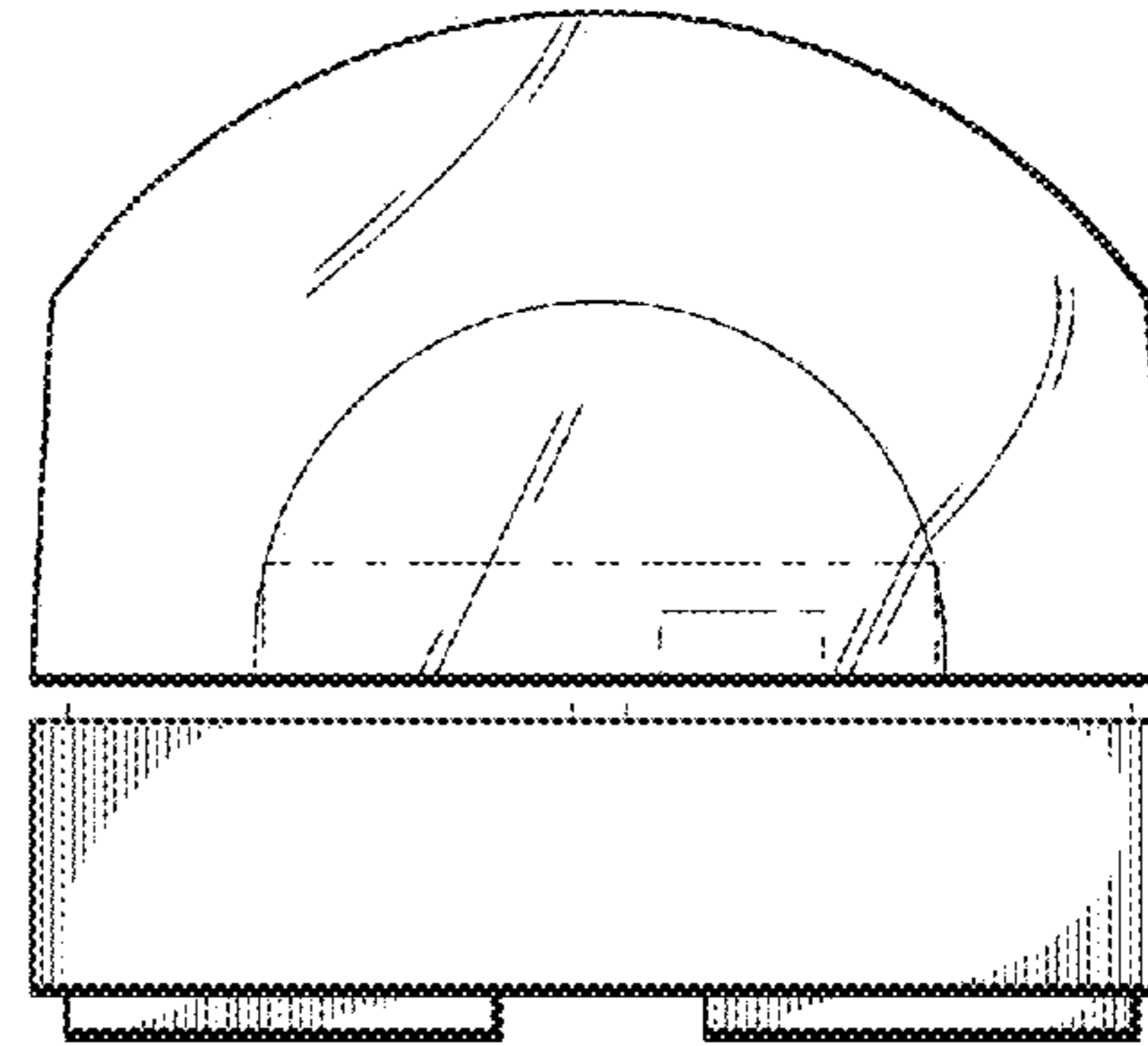


FIG. 12

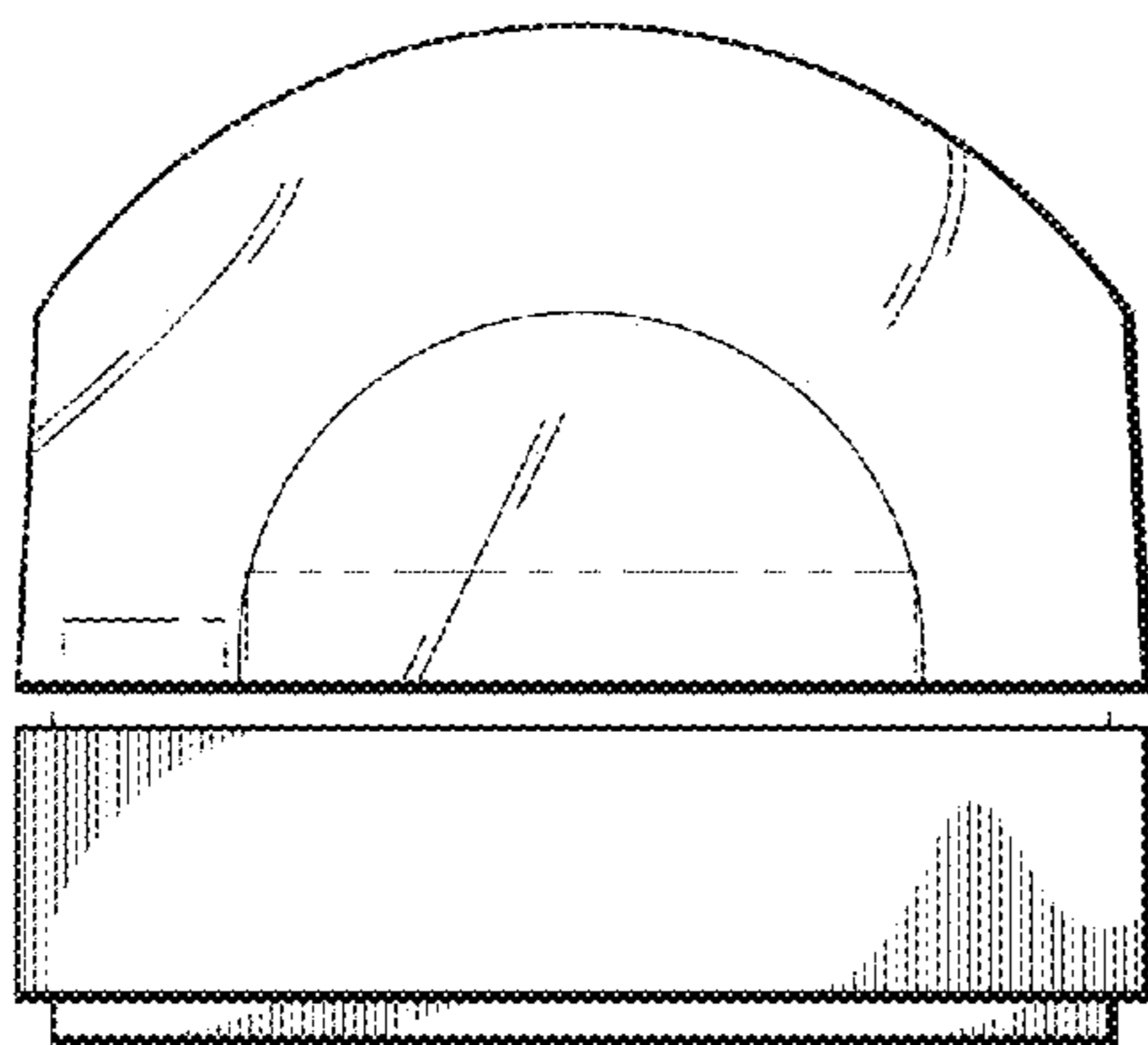


FIG. 13

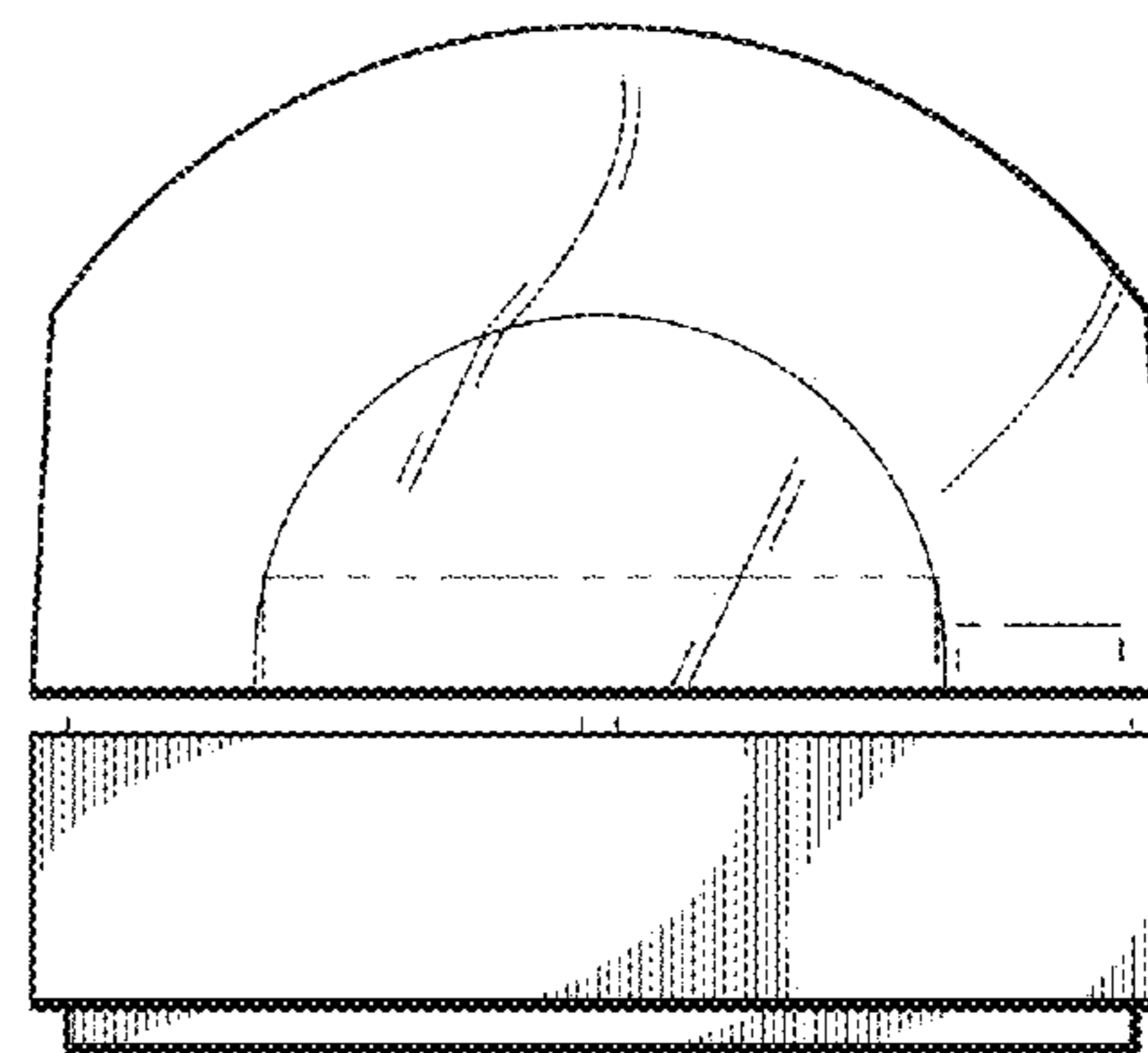


FIG. 14

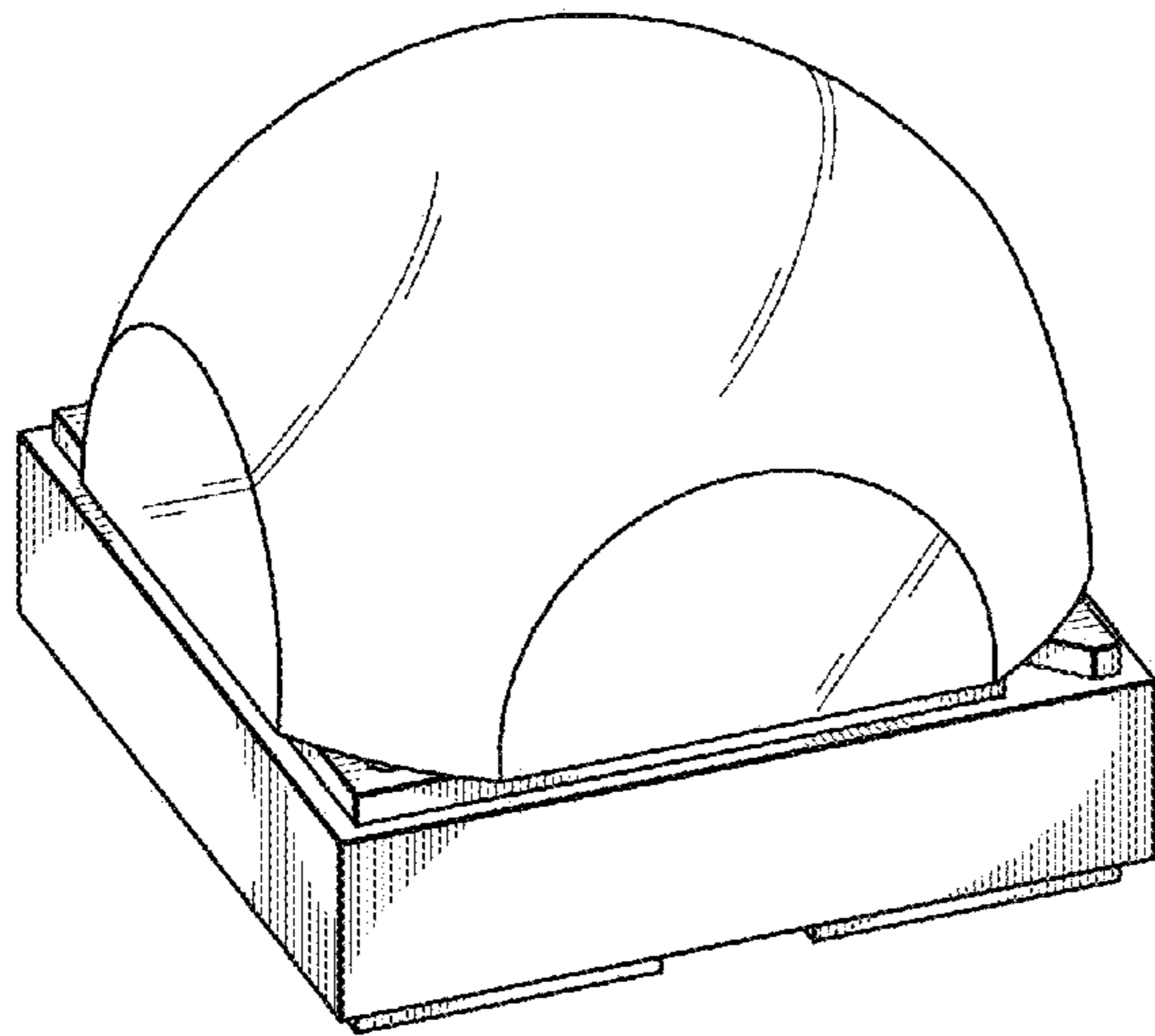


FIG. 15

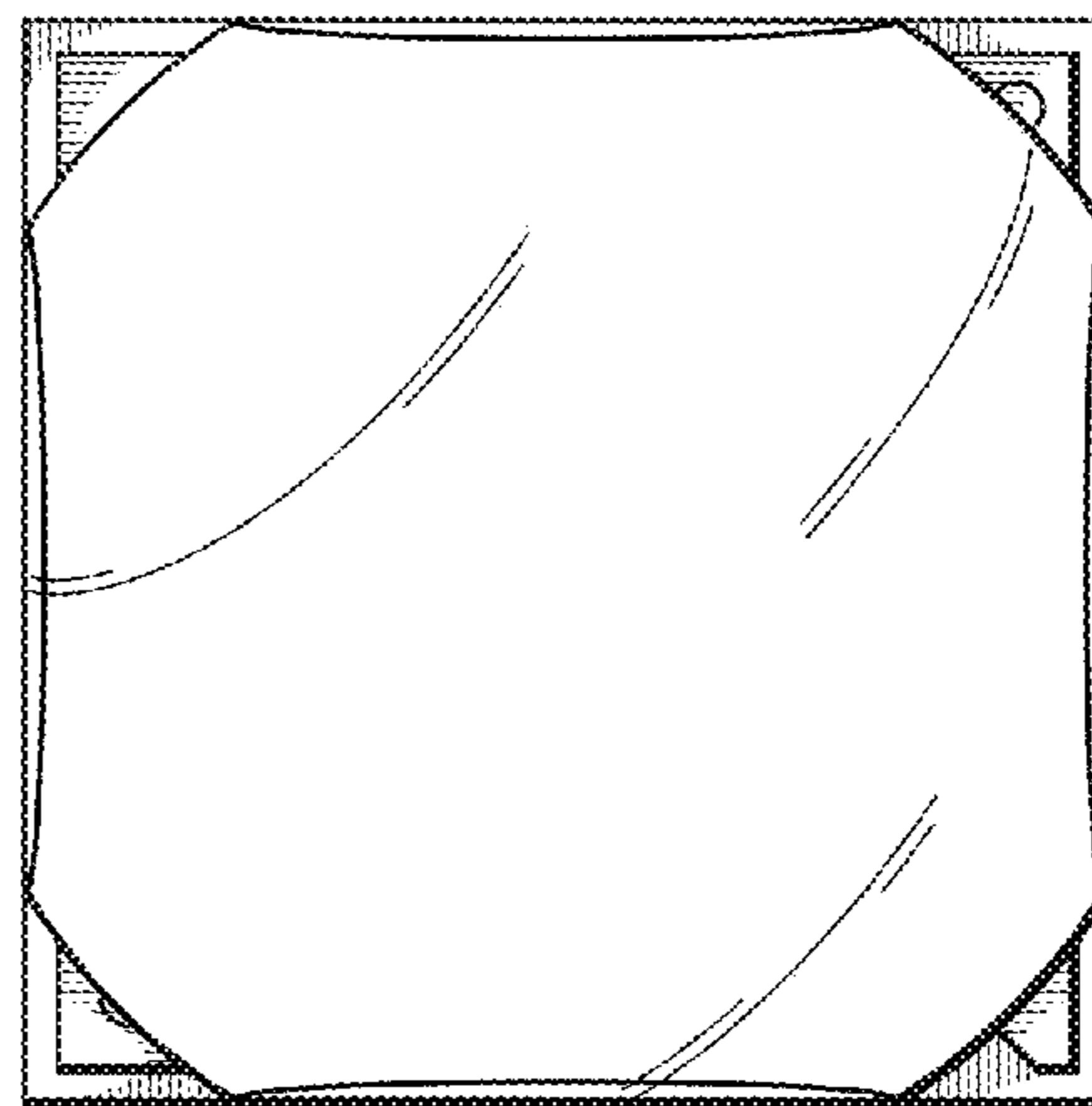


FIG. 16

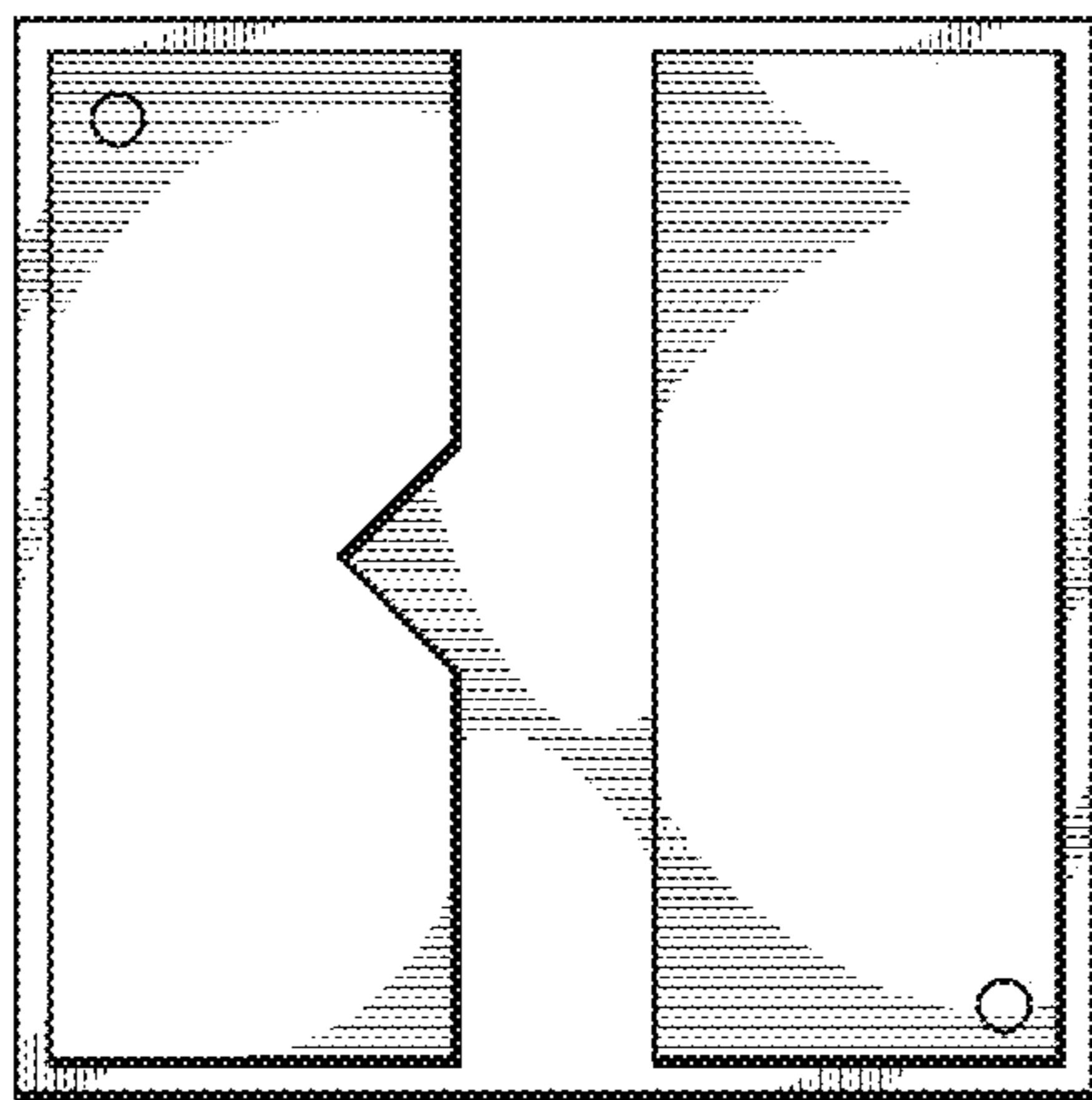


FIG. 17

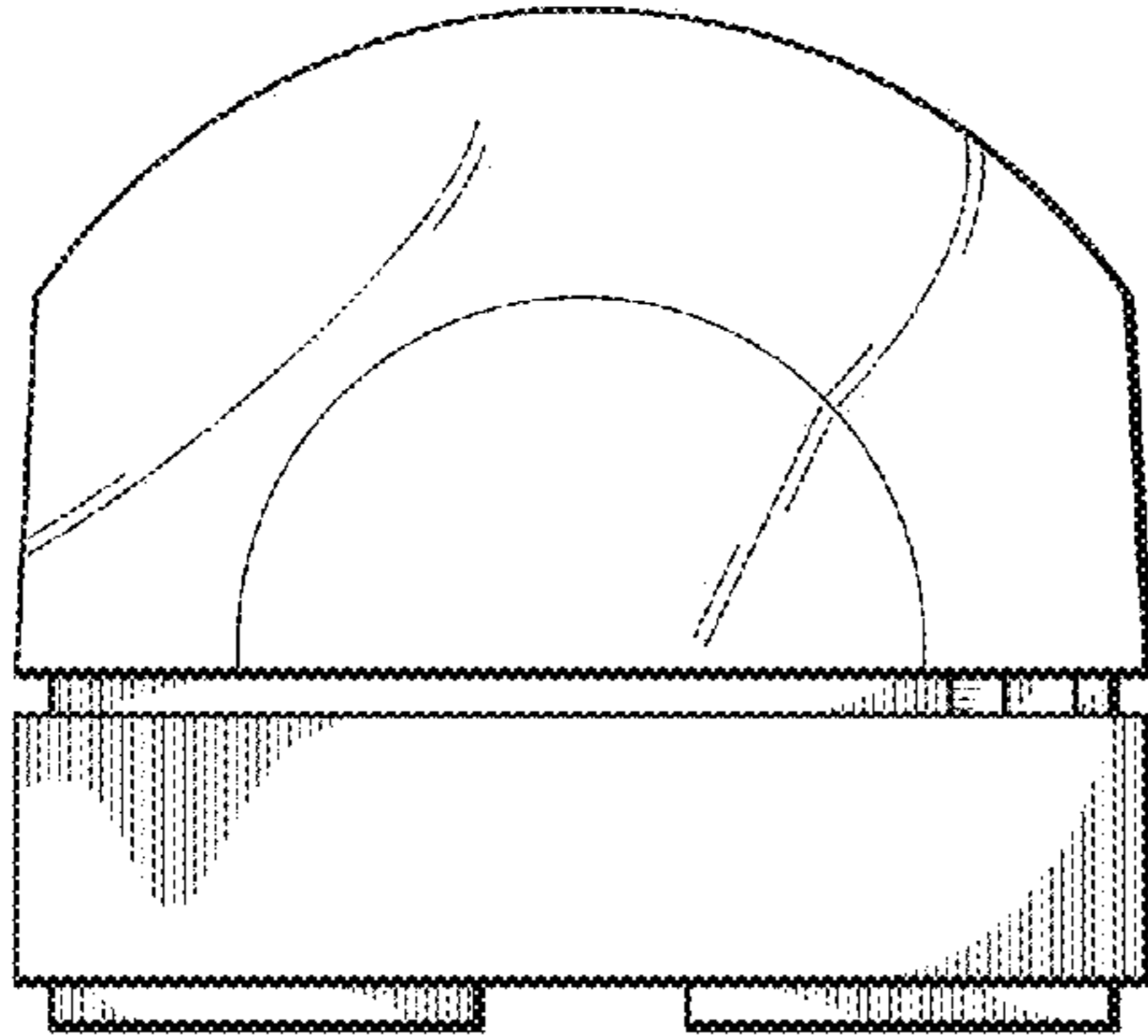


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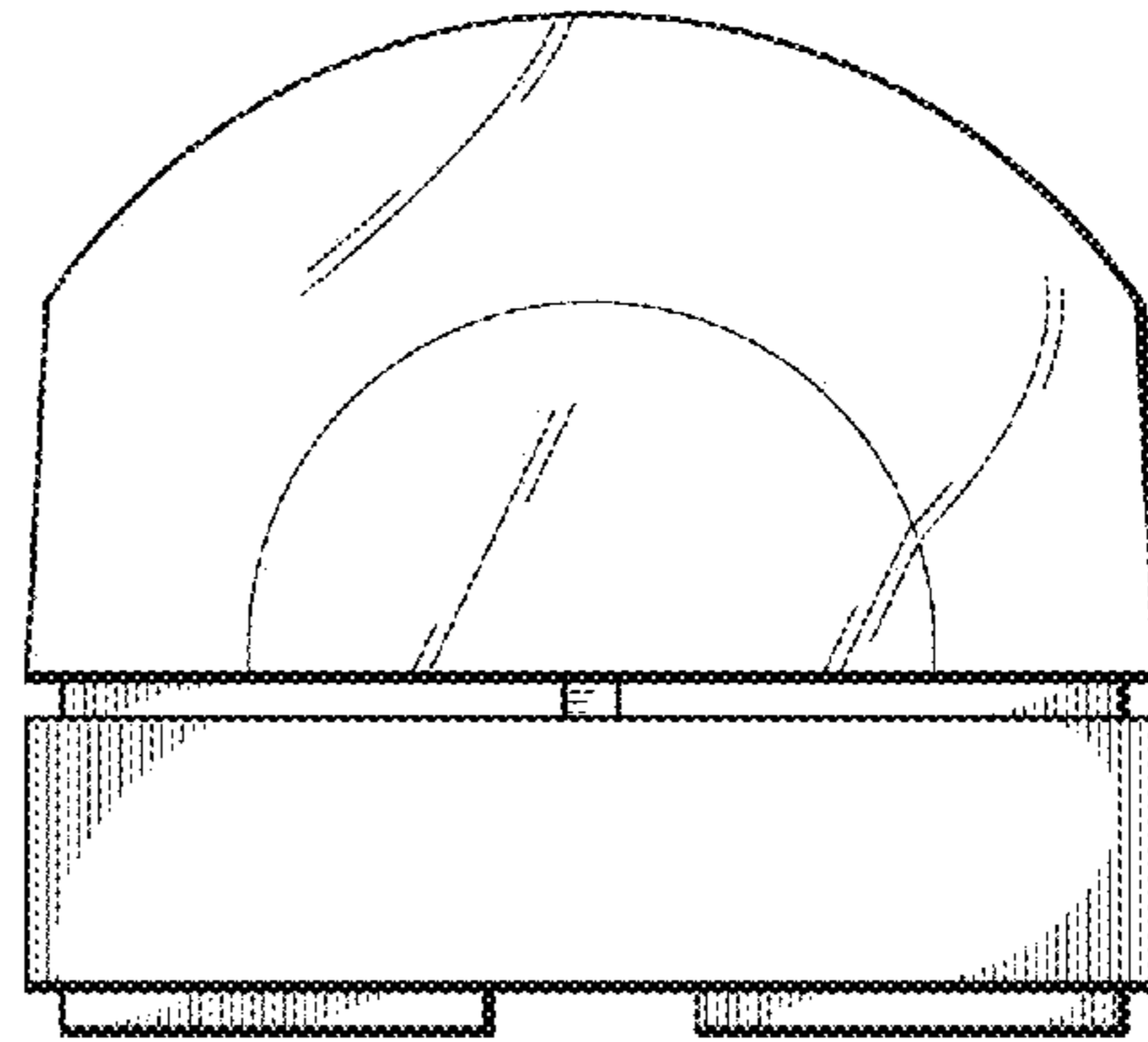


FIG. 19

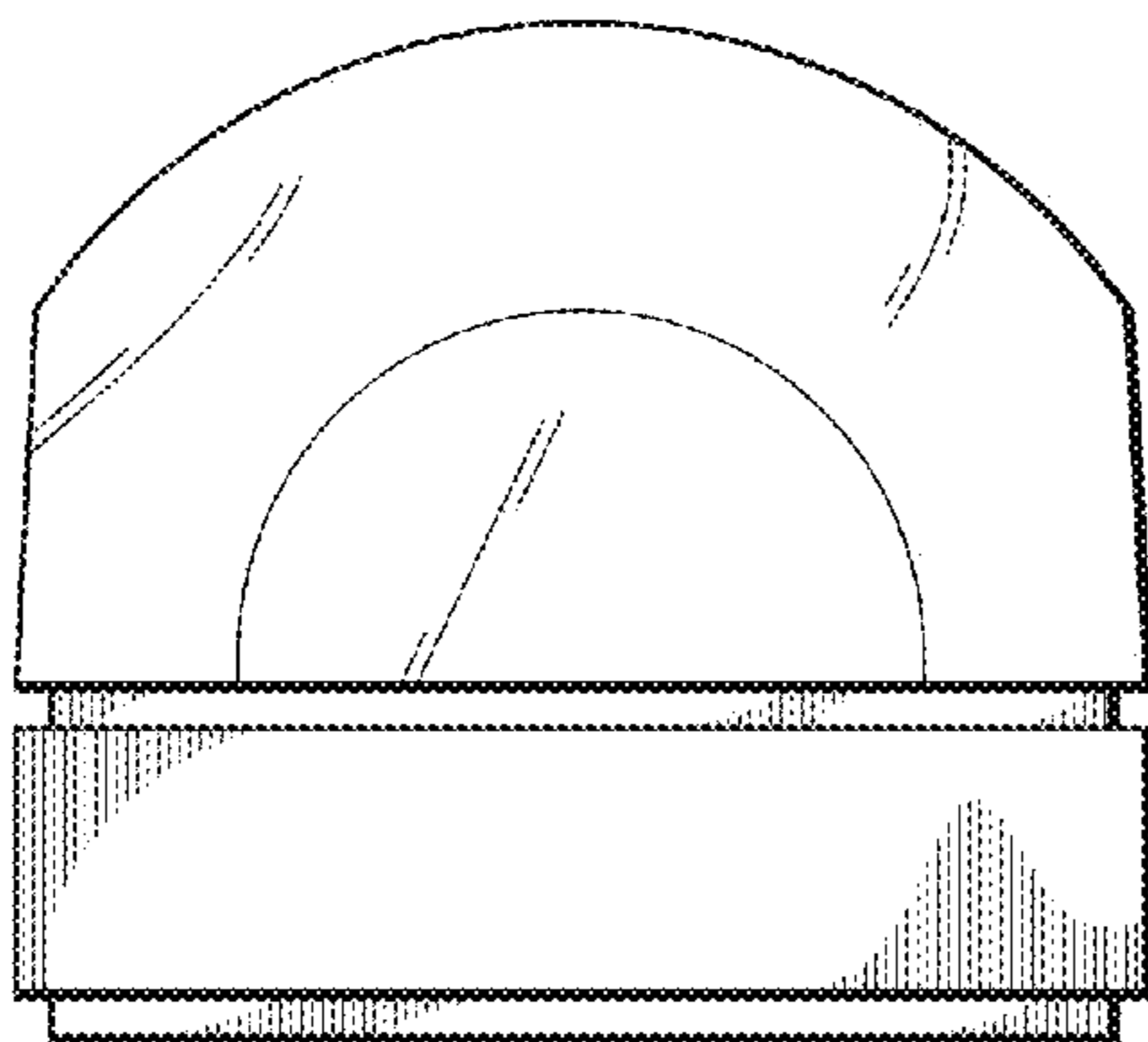


FIG. 20

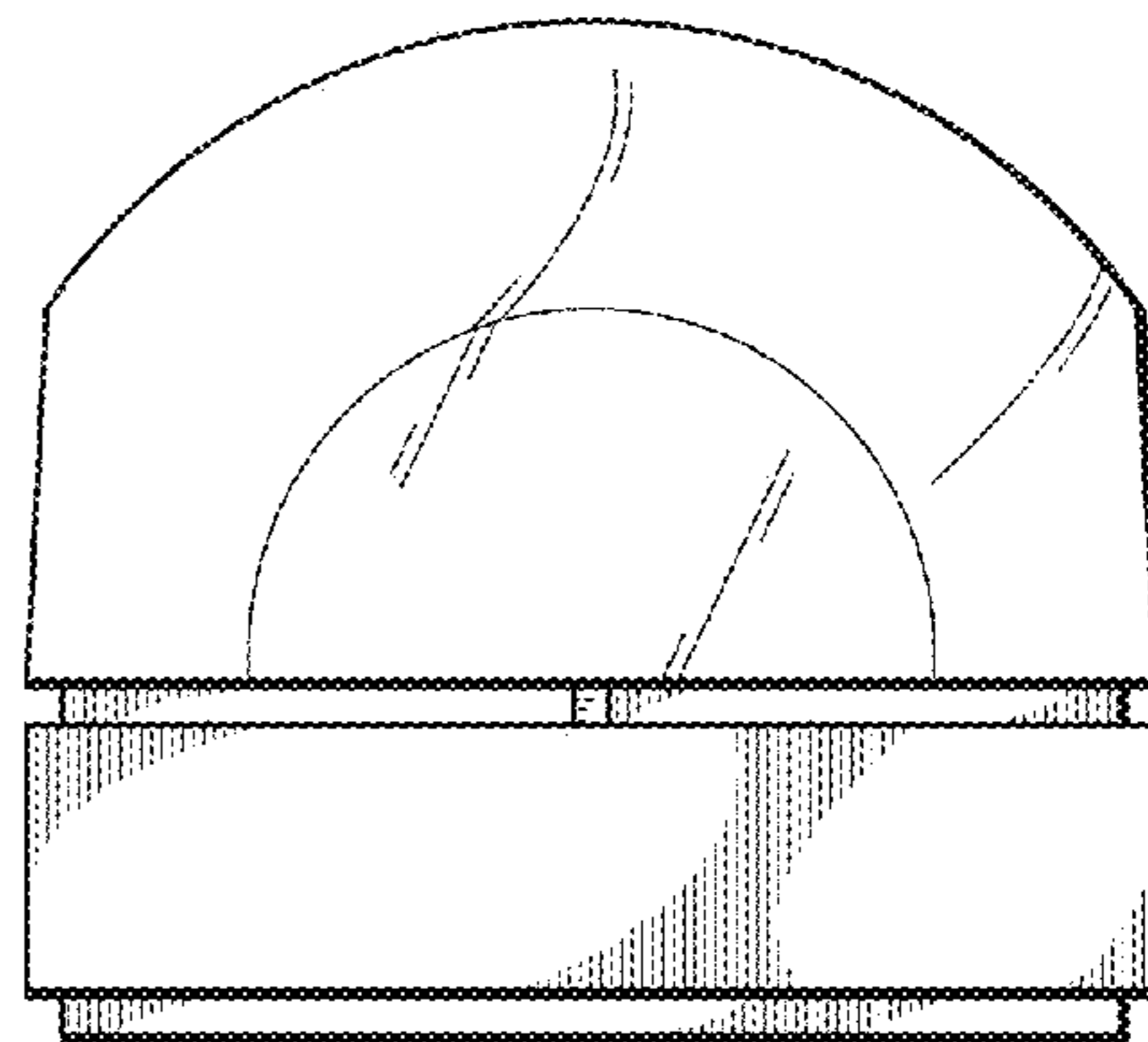


FIG. 21

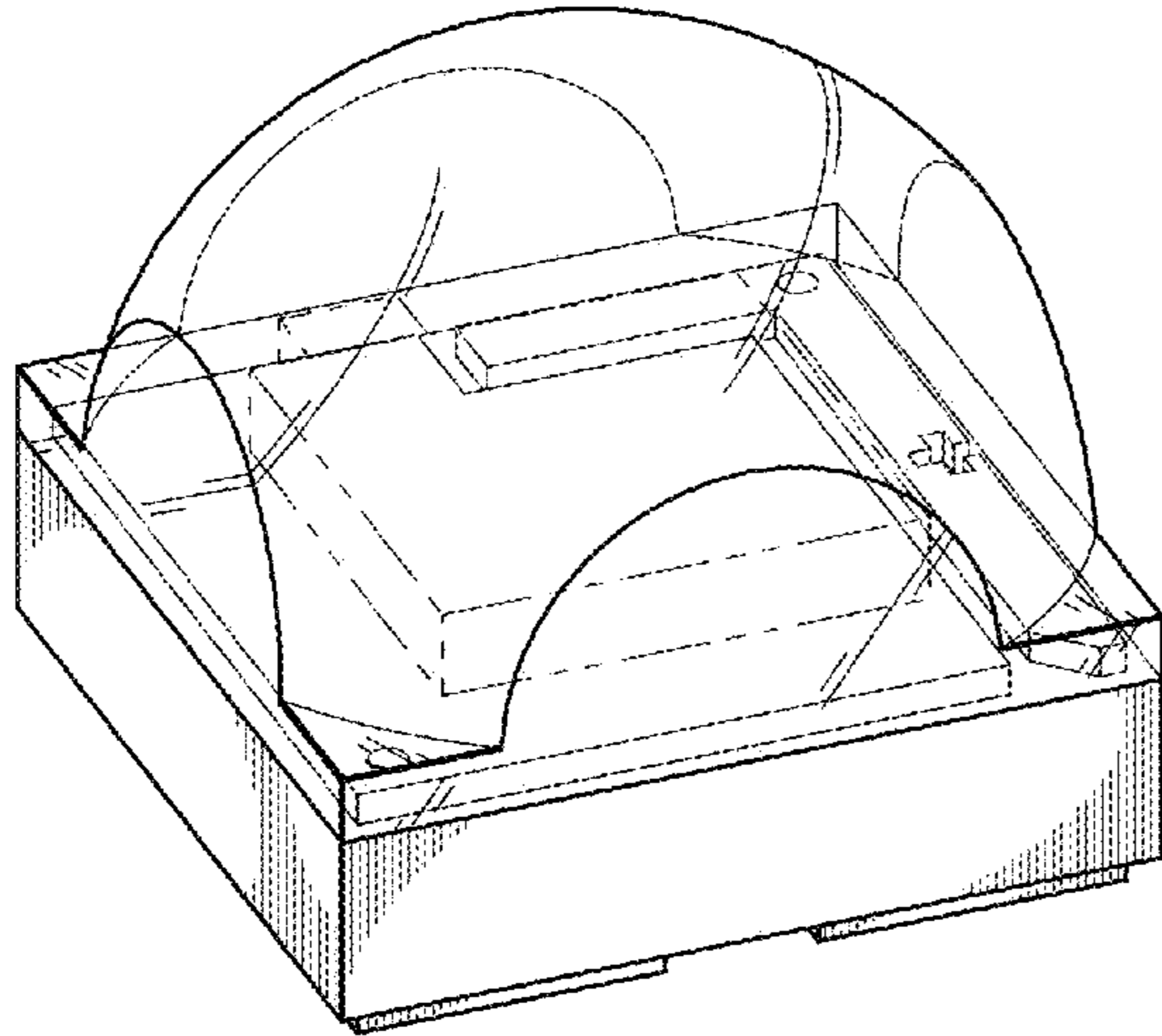


FIG. 22

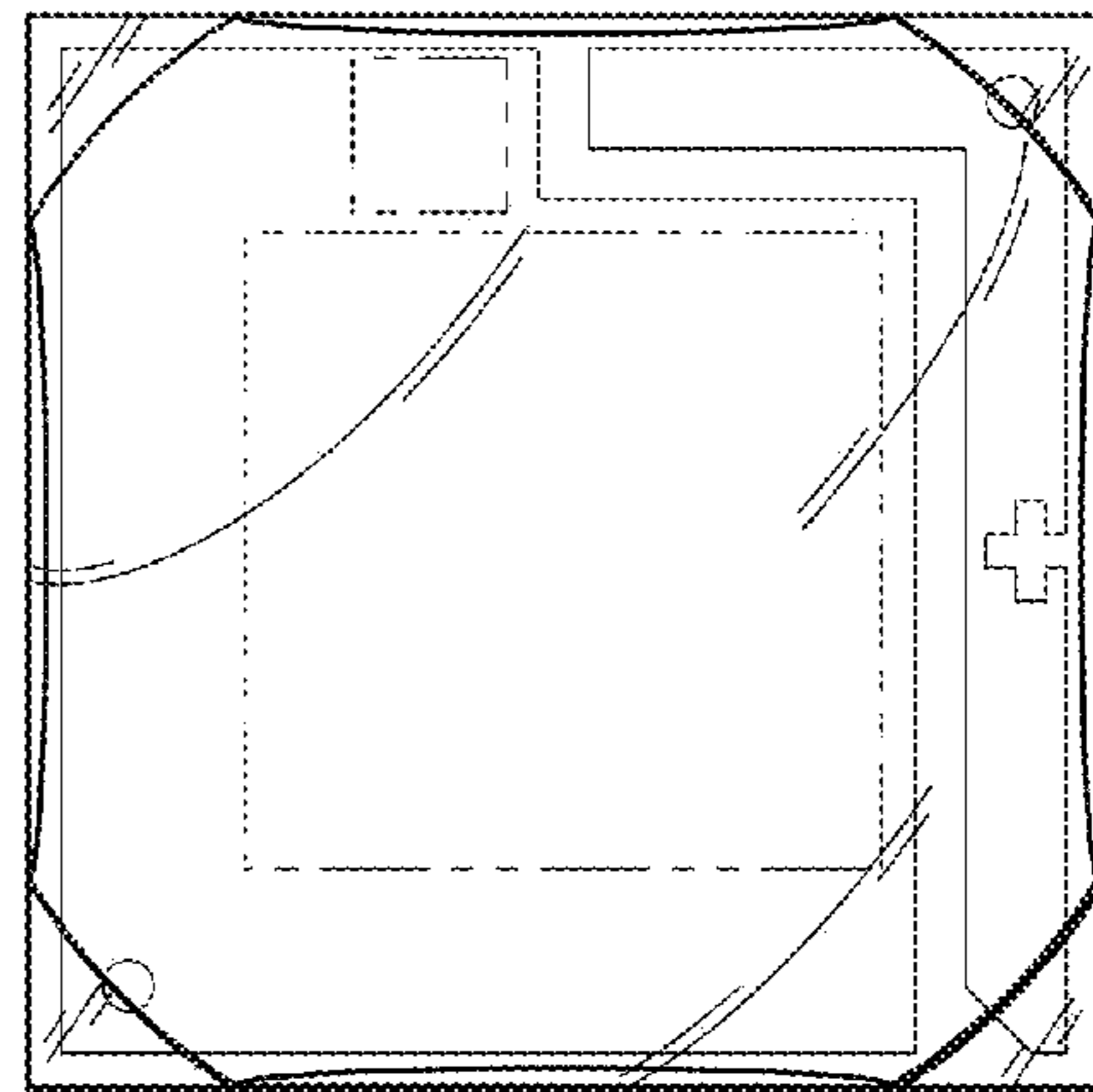


FIG. 23

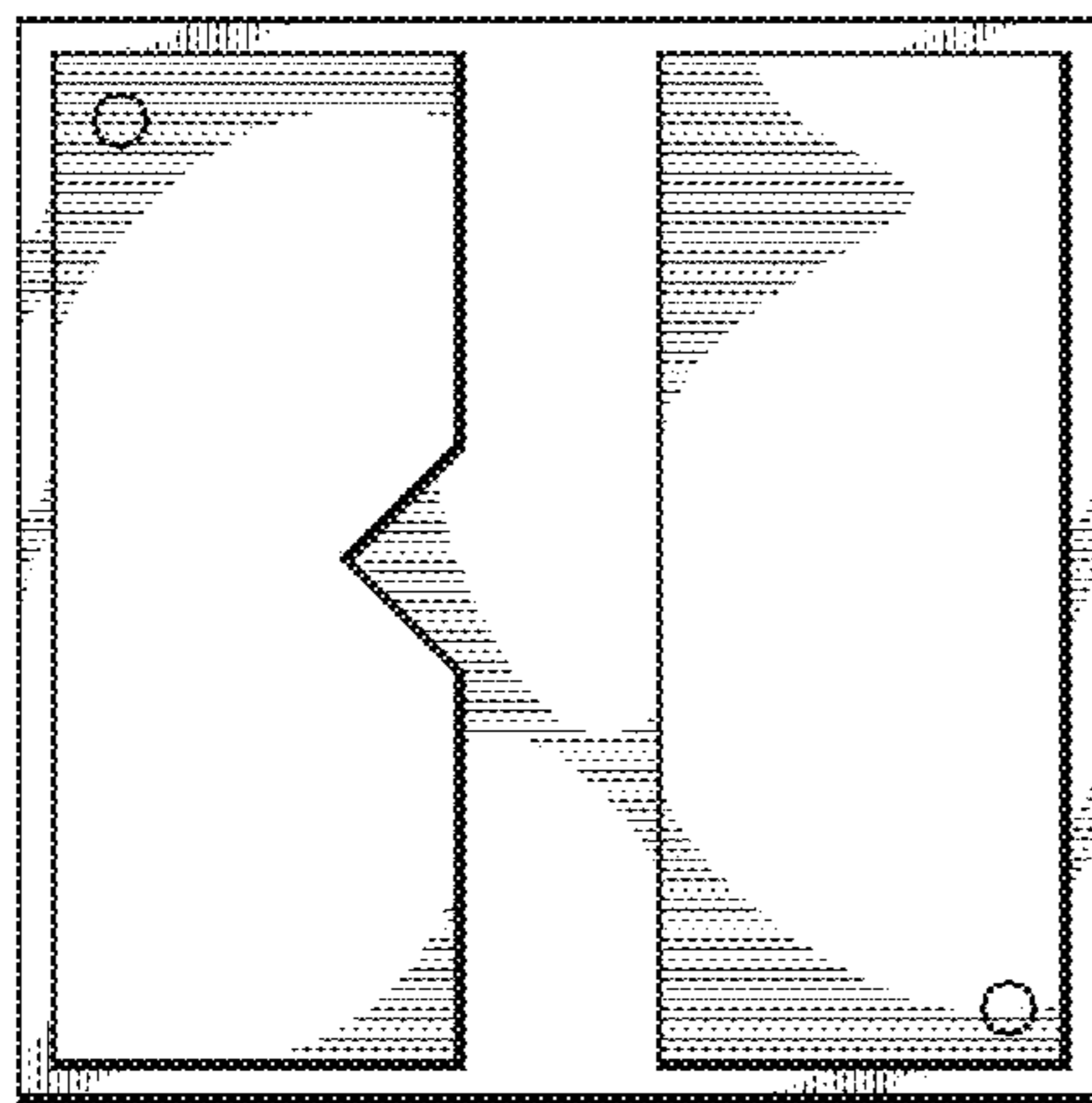


FIG. 24

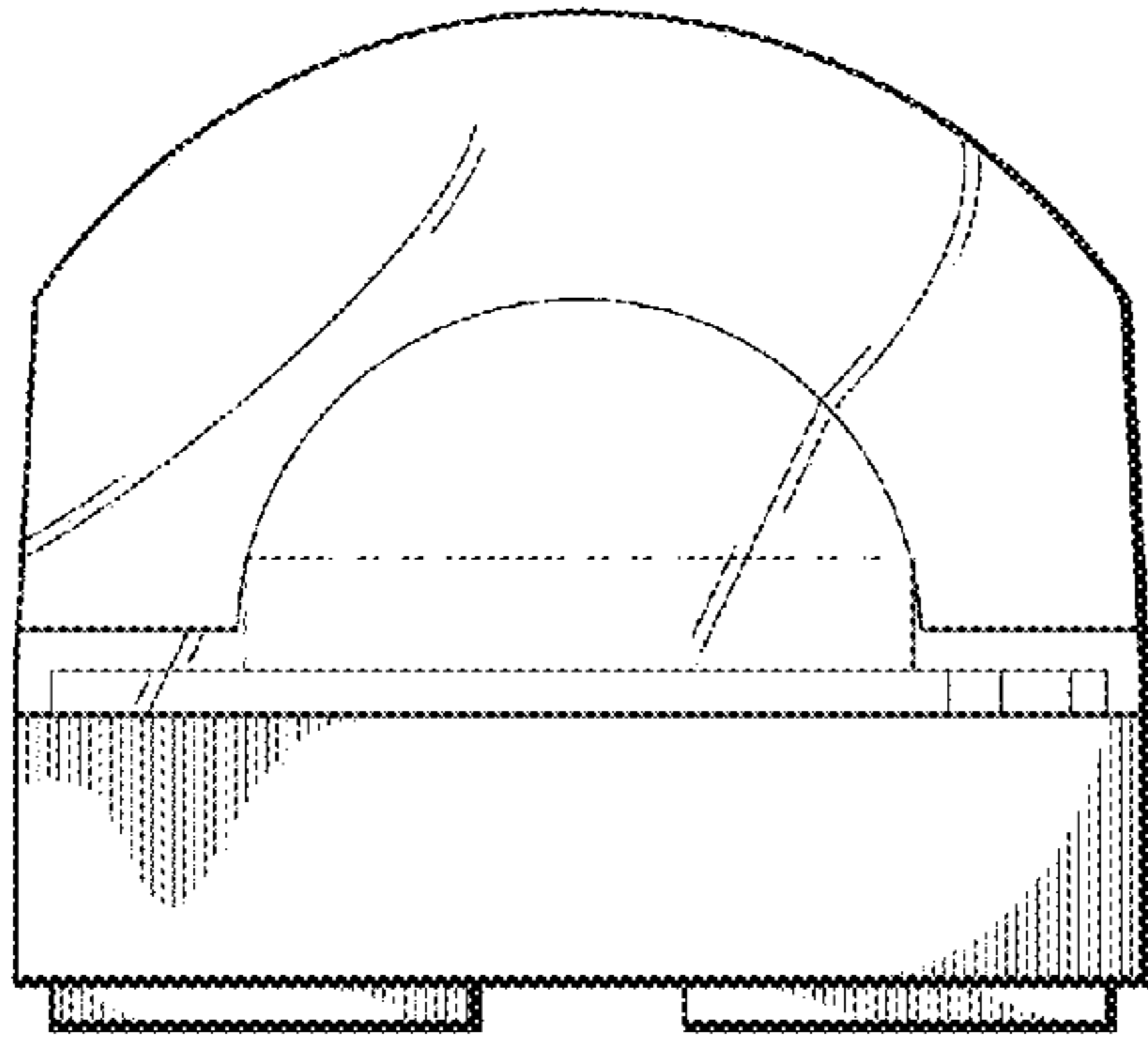


FIG. 25

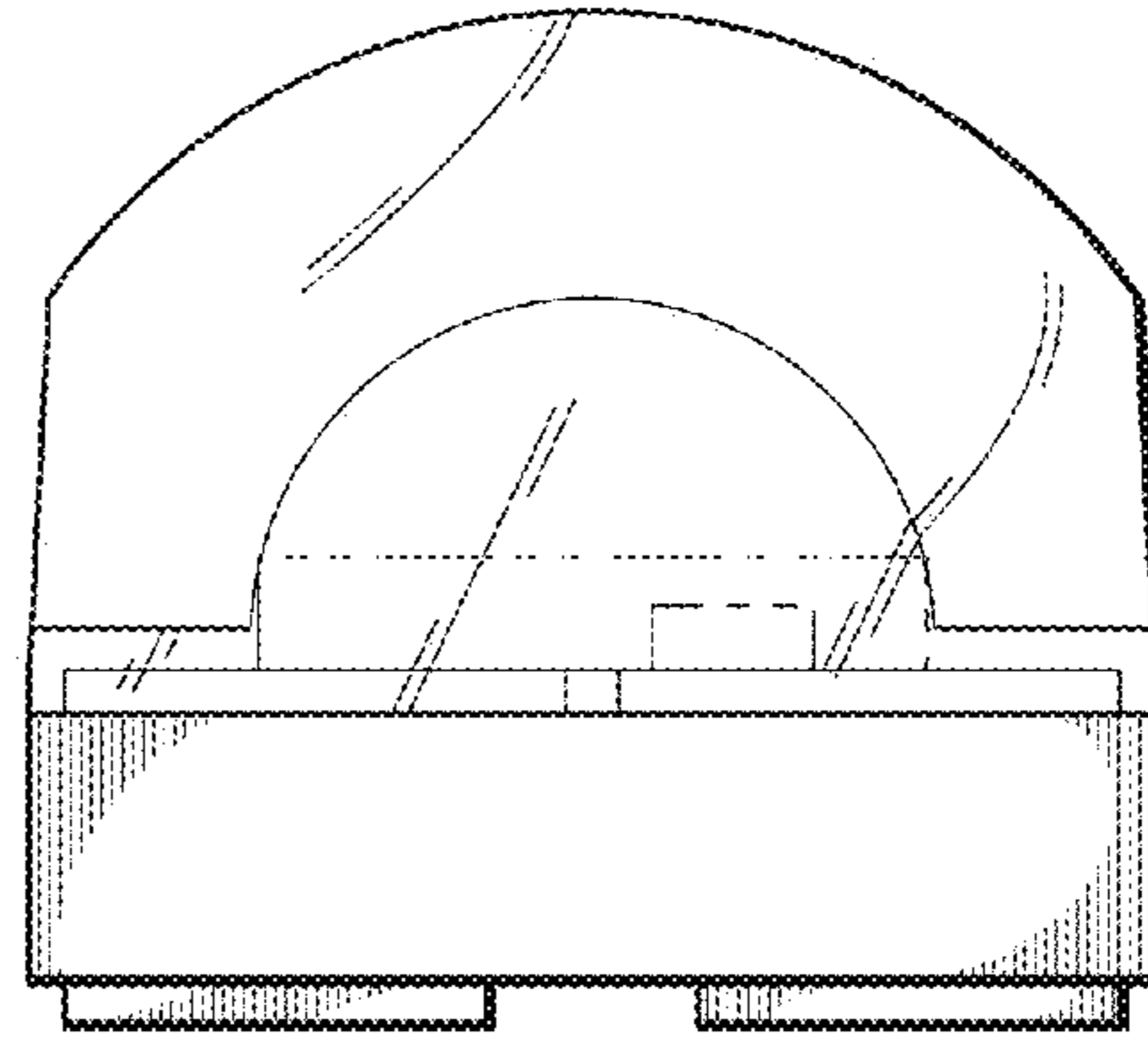


FIG. 26

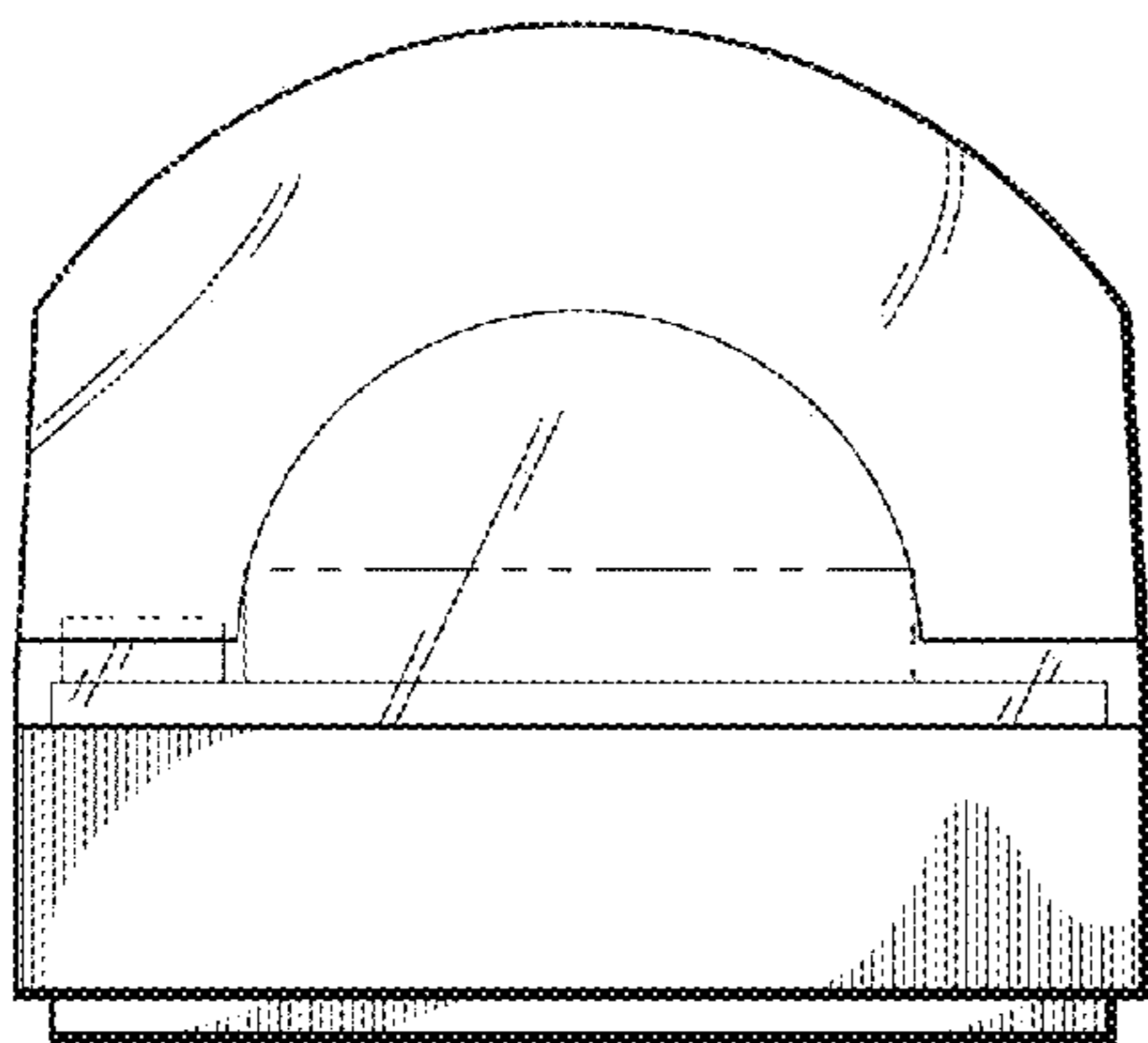


FIG. 27

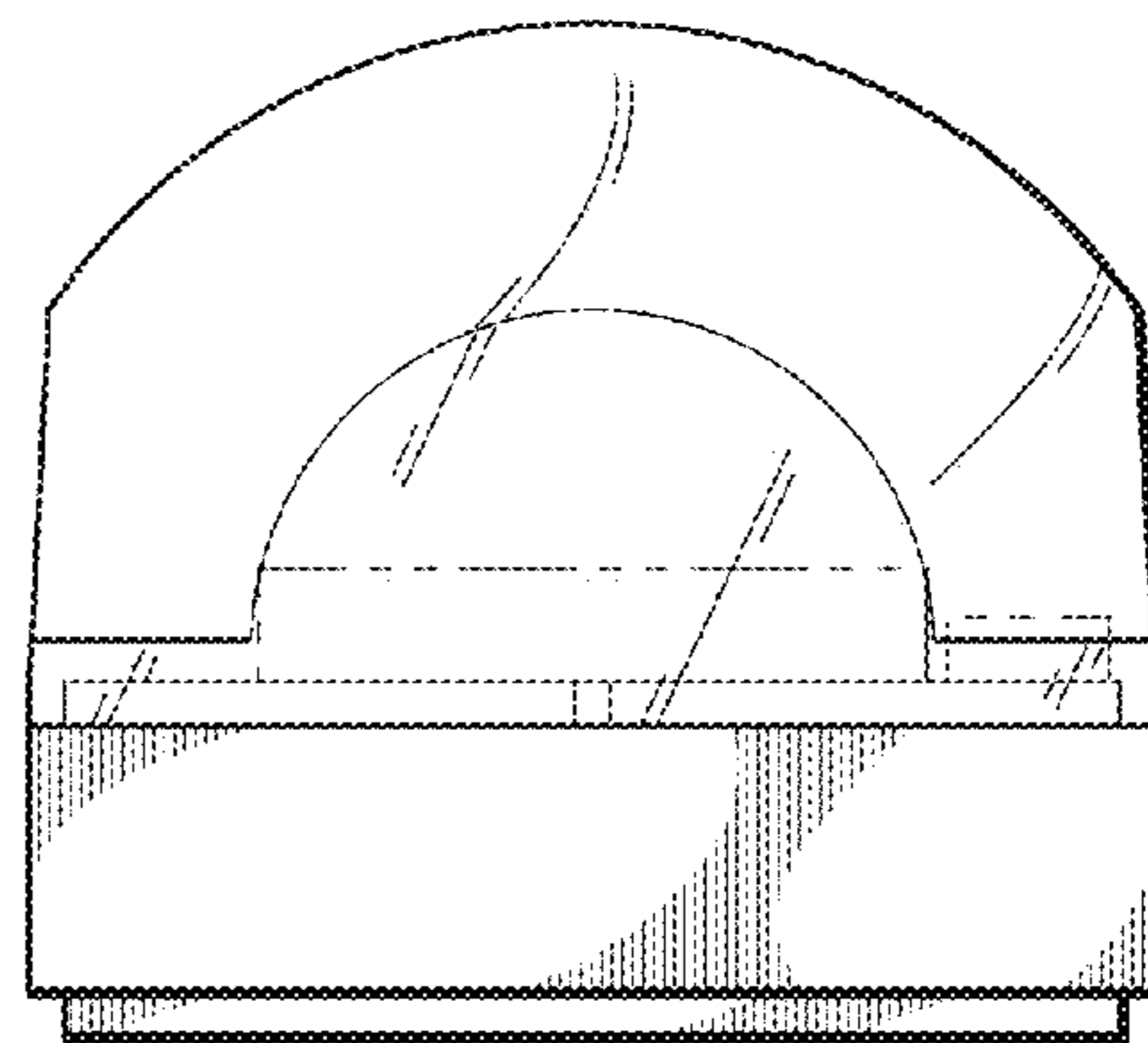


FIG. 28

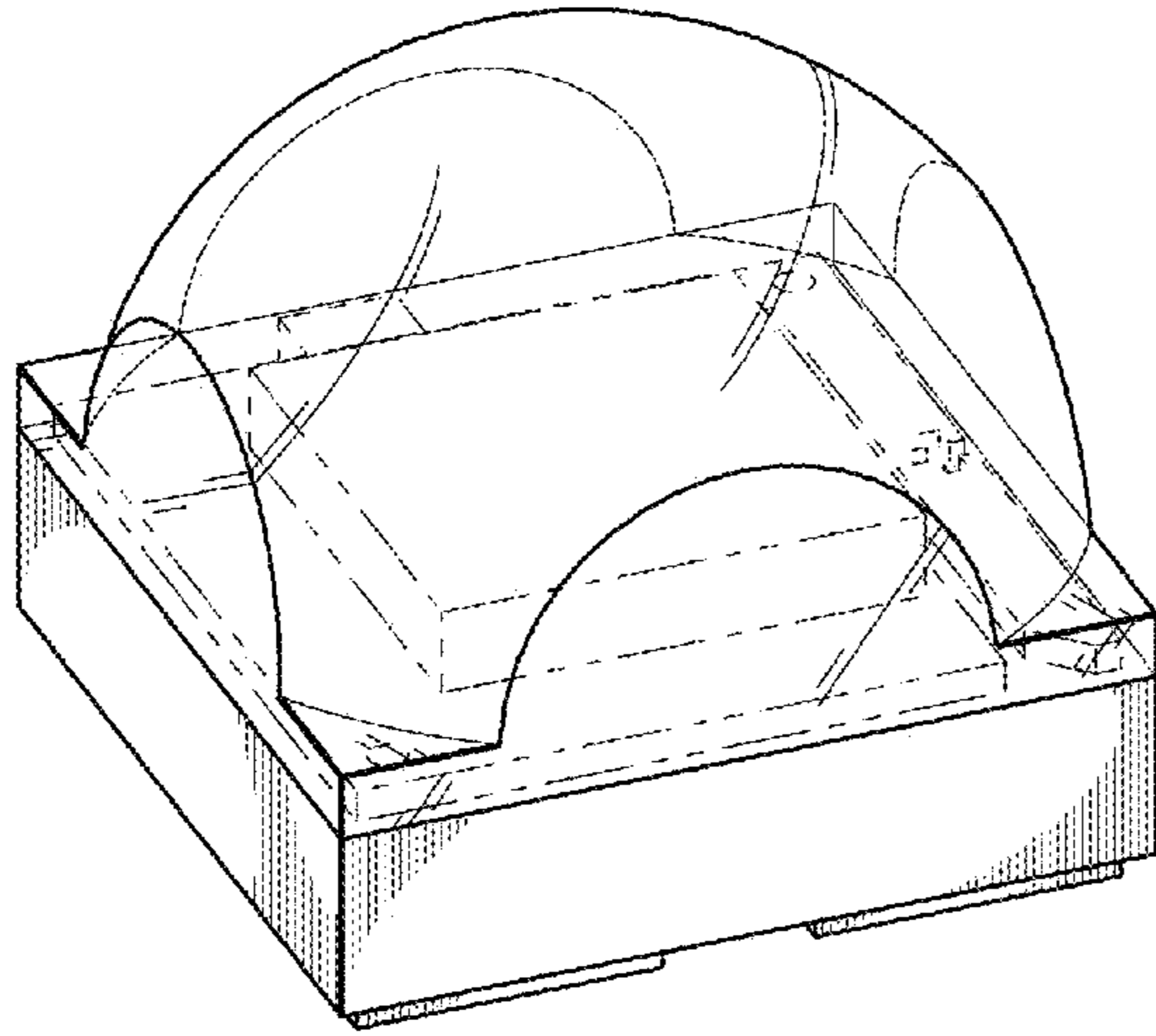


FIG. 29

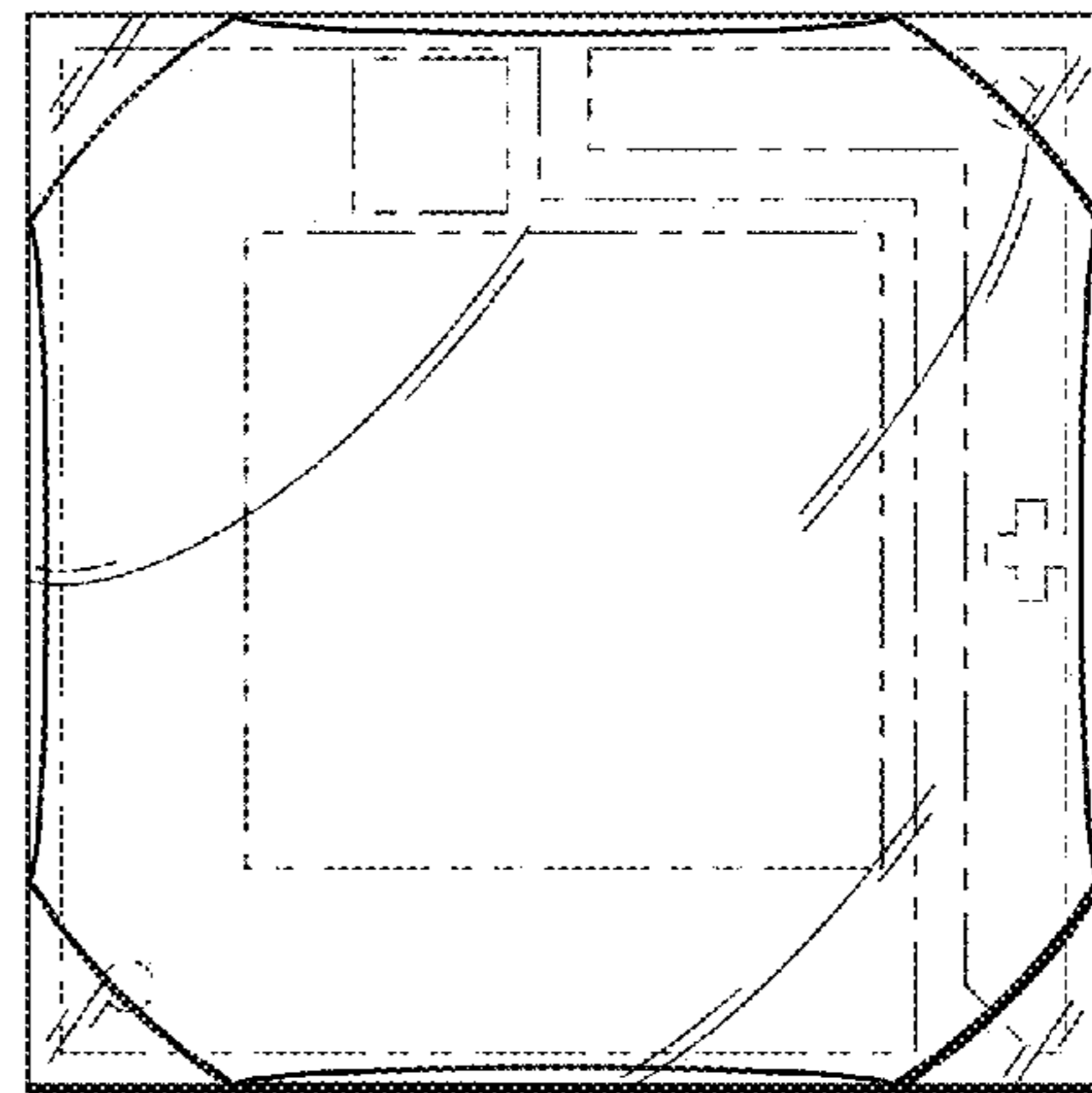


FIG. 30

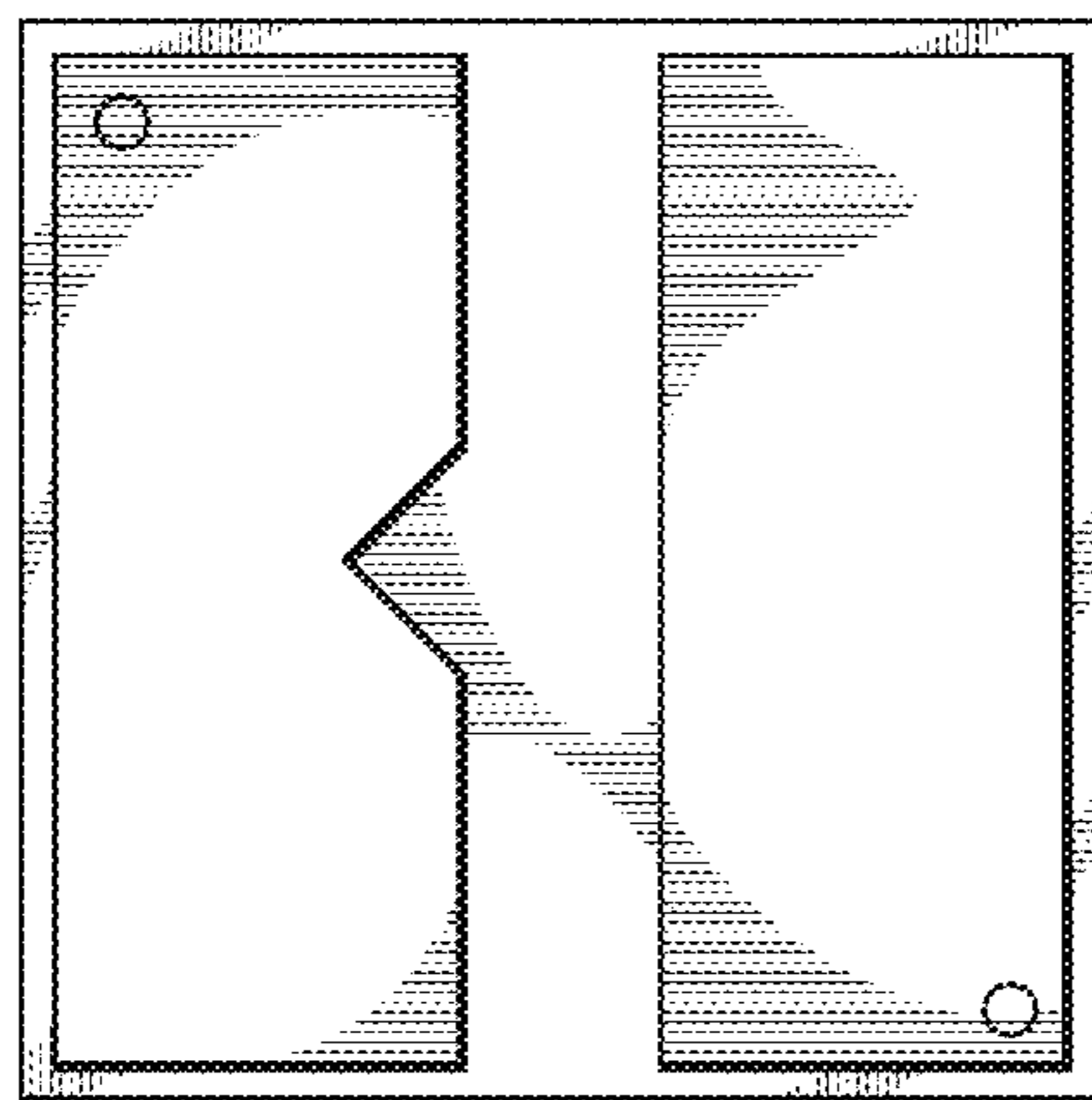


FIG. 31

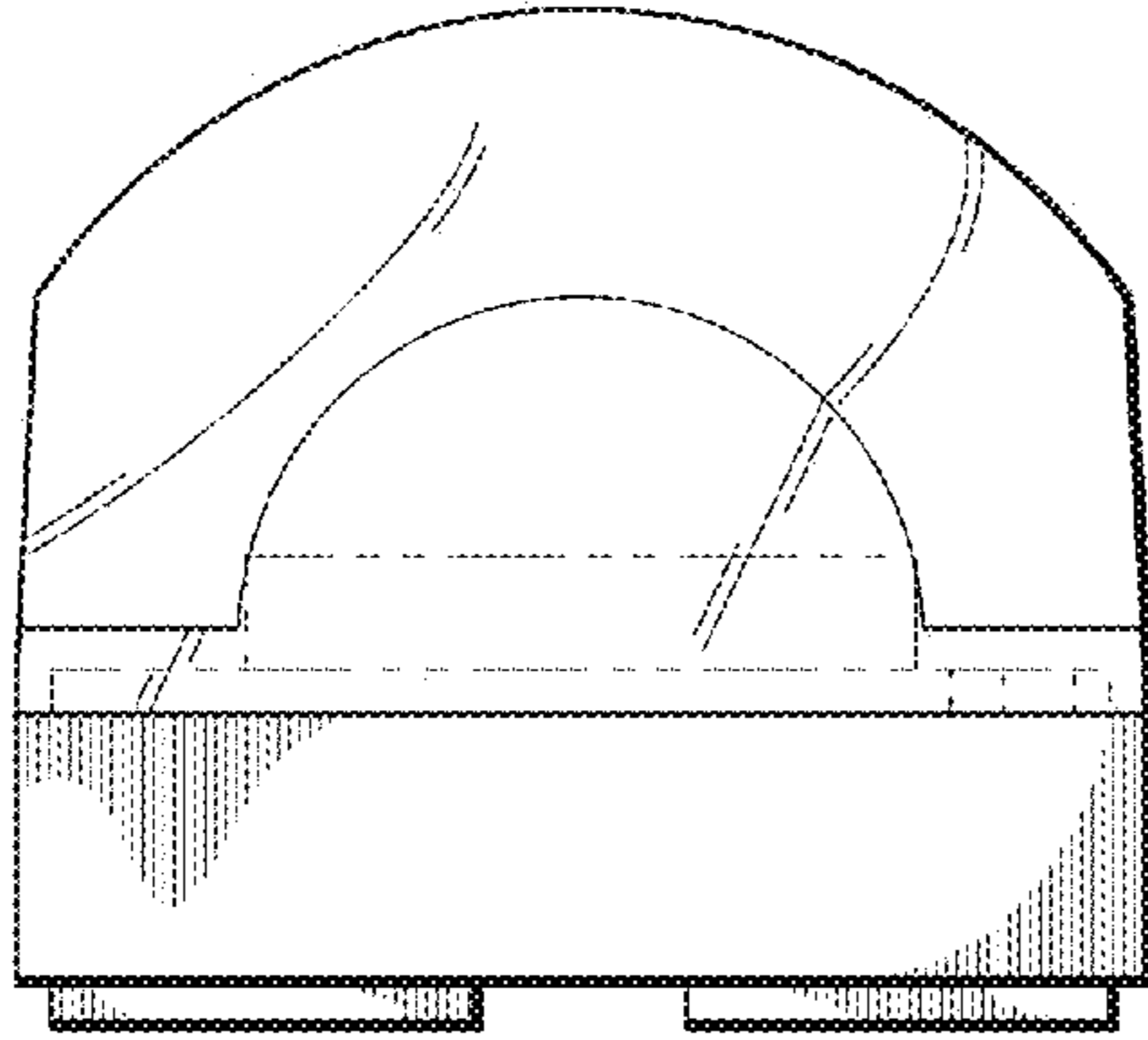


FIG. 32

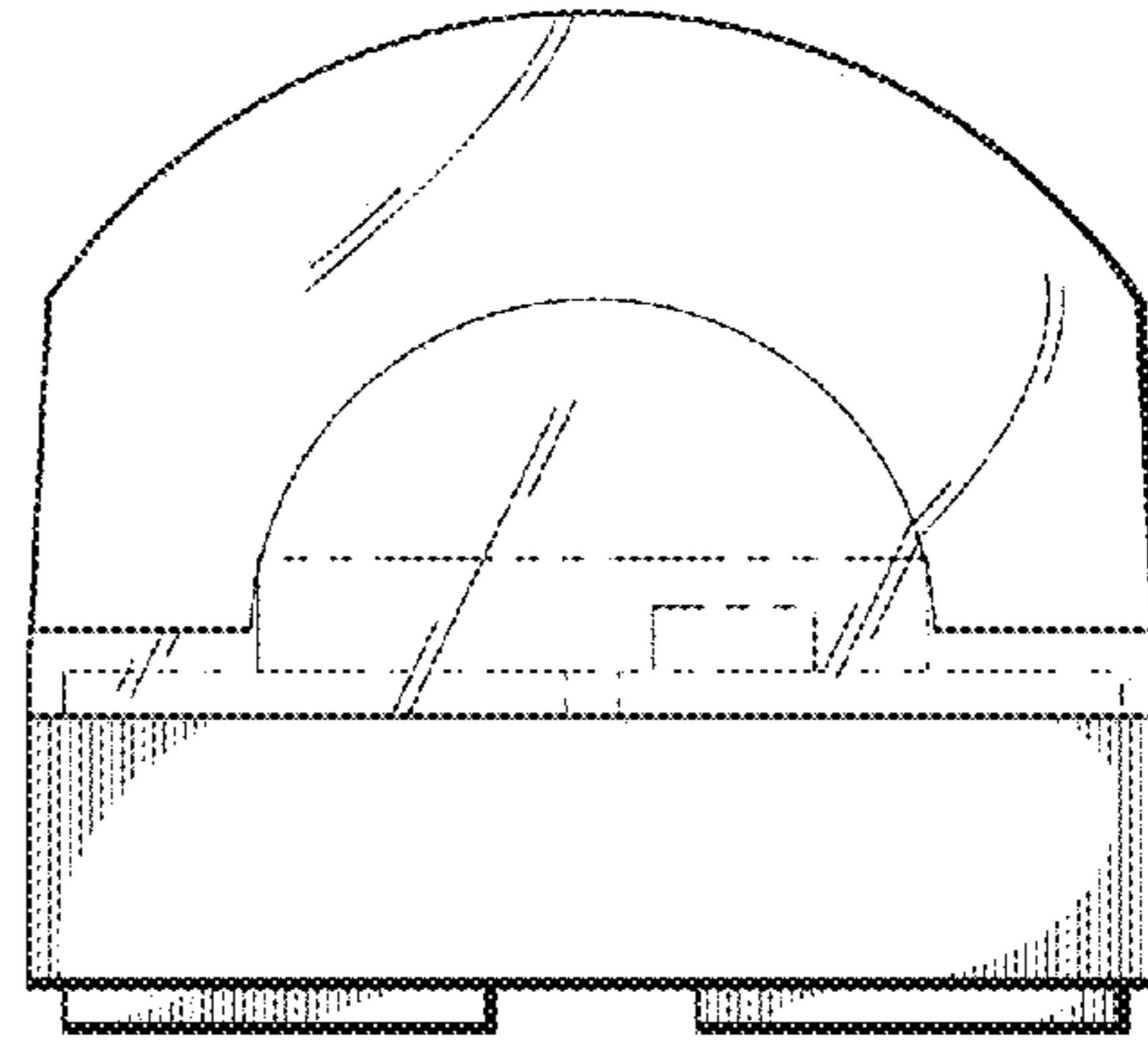


FIG. 33

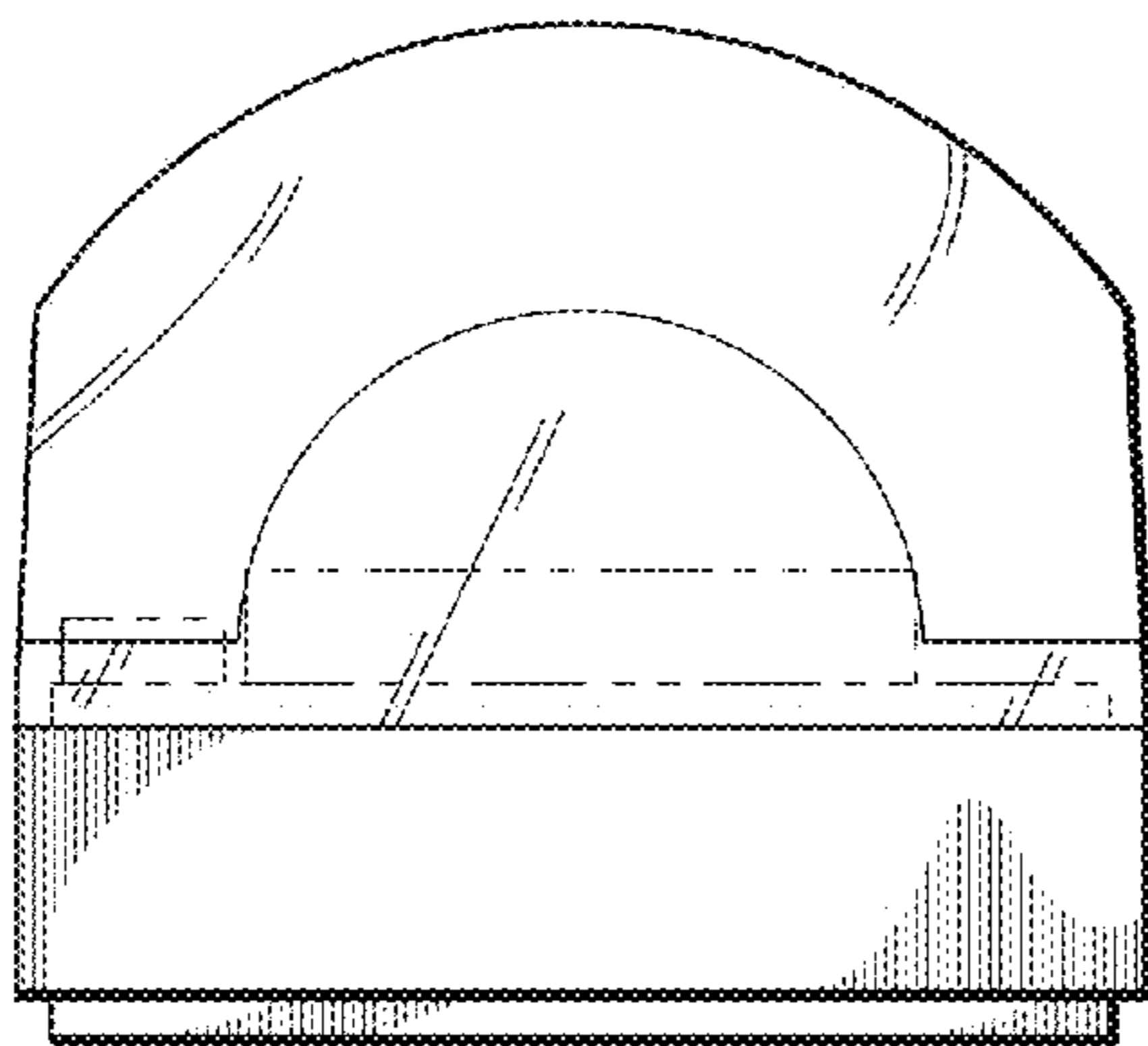


FIG. 34

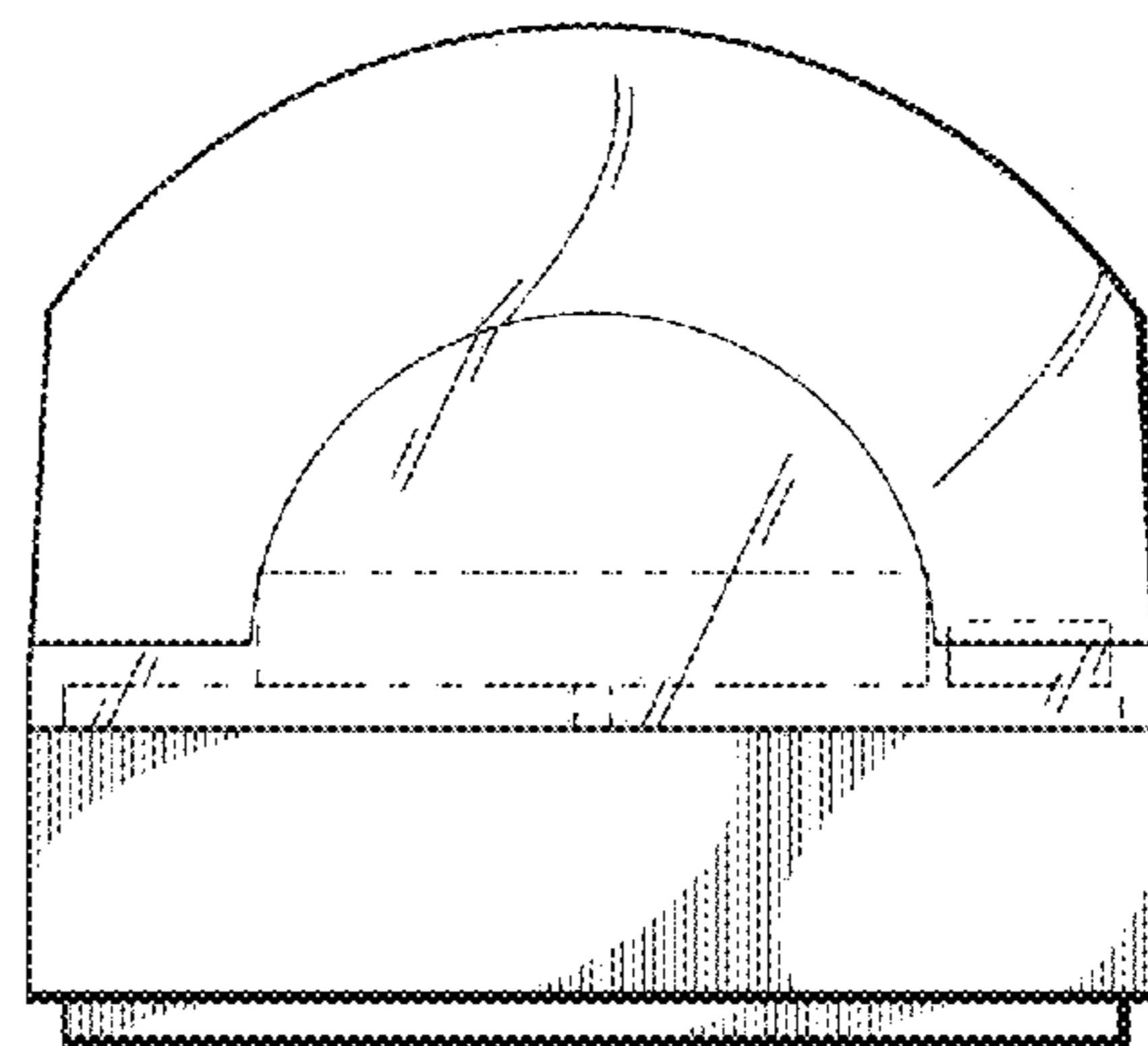


FIG. 35

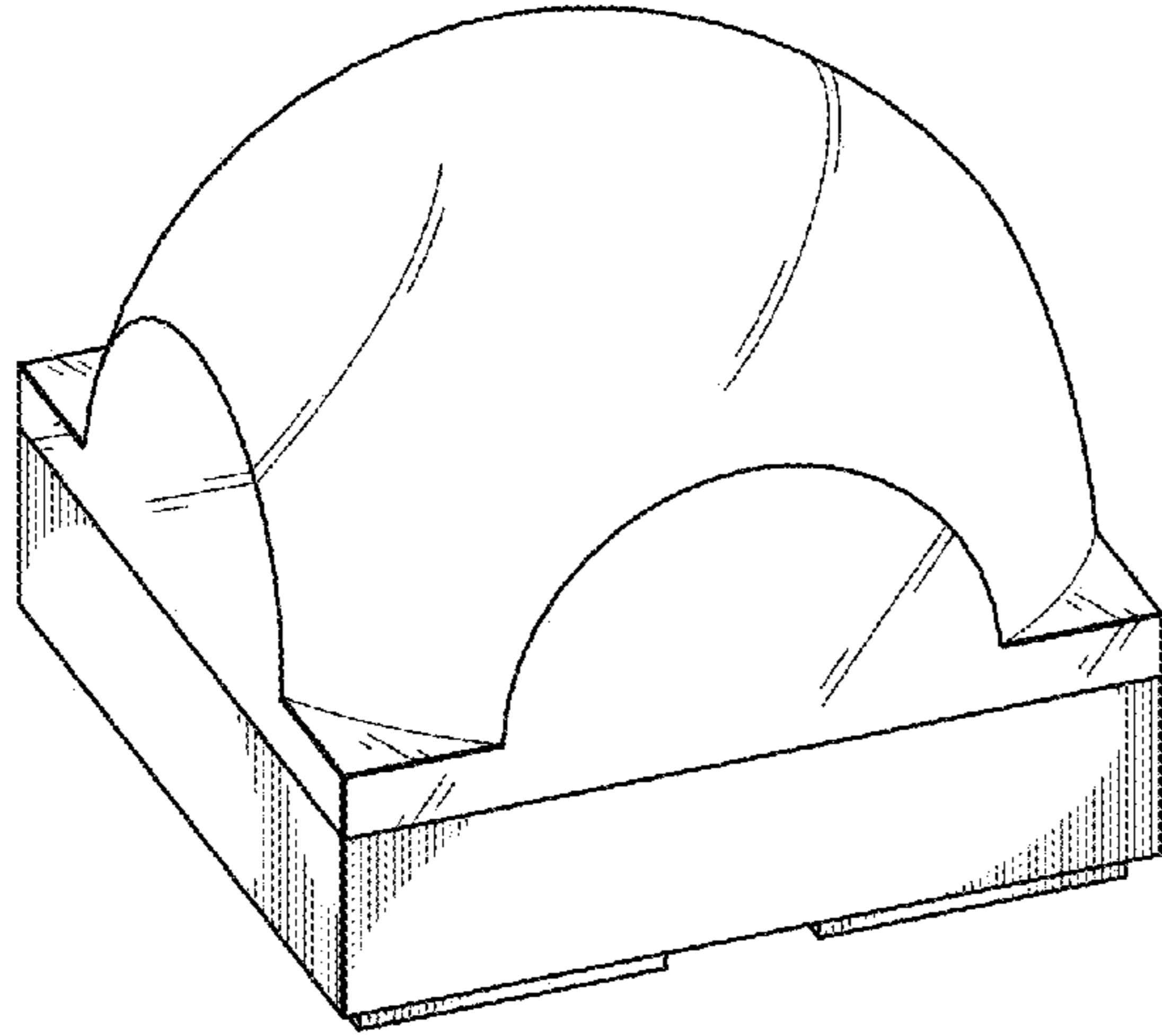


FIG. 36

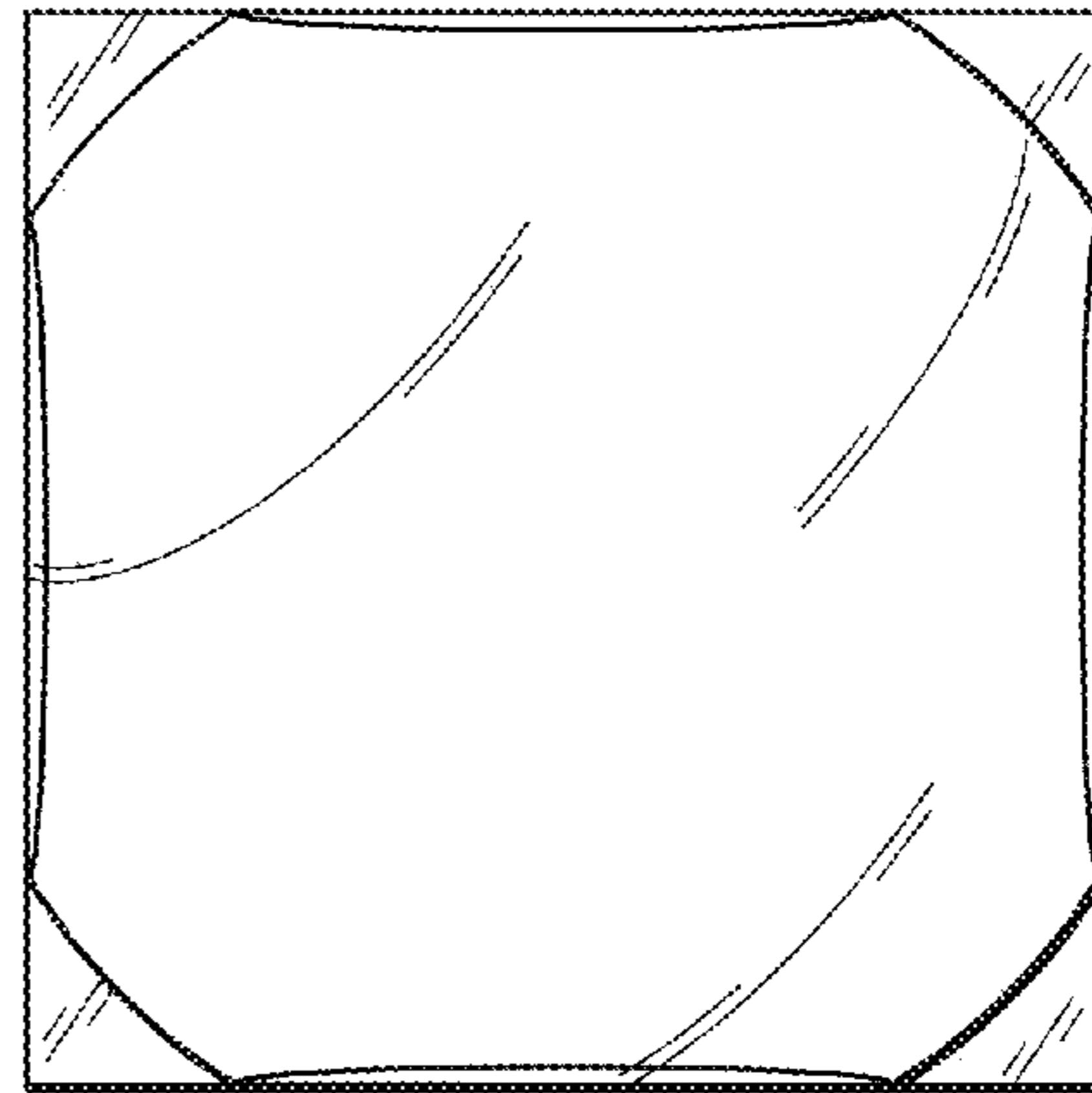


FIG. 37

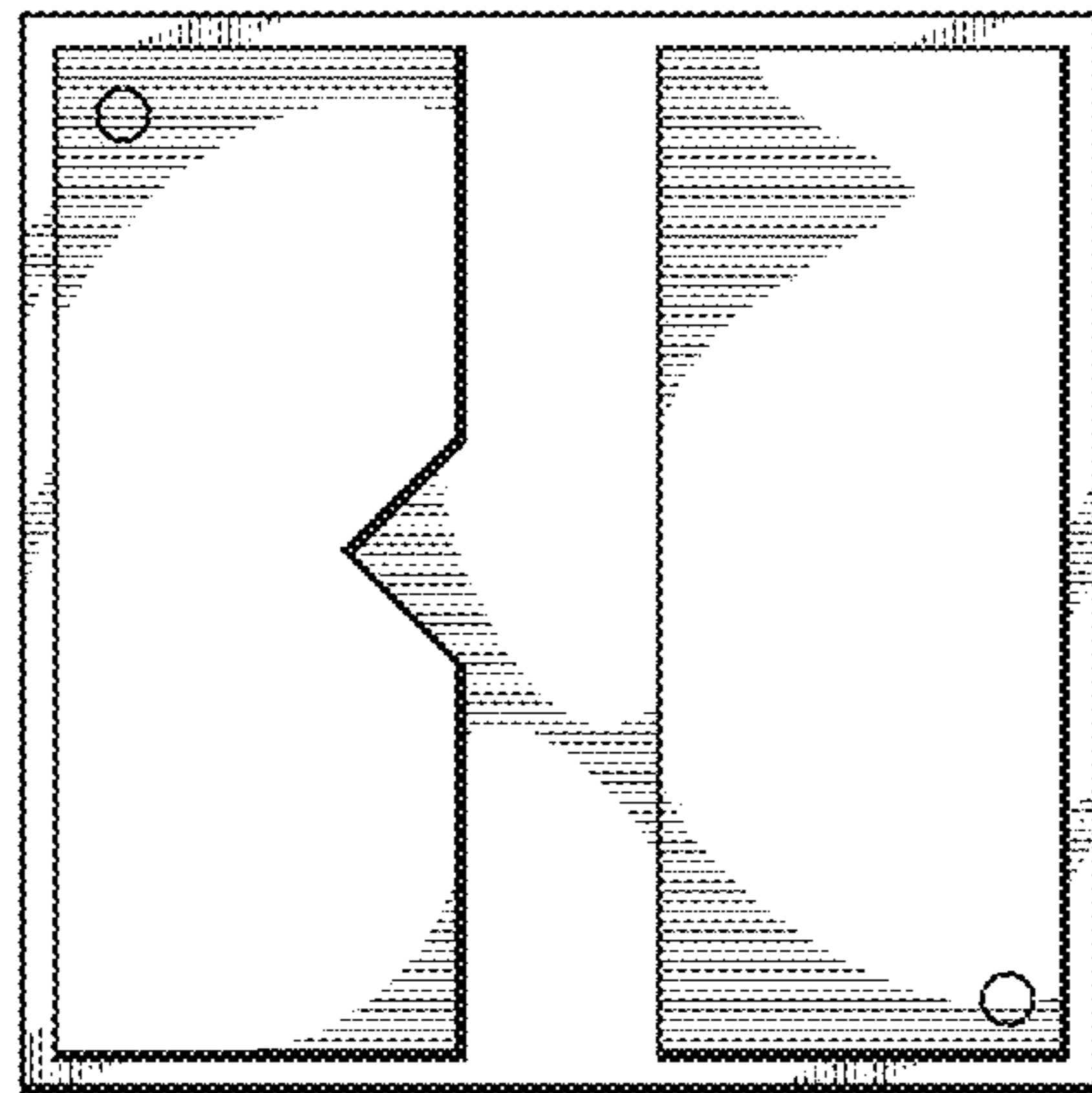


FIG. 38

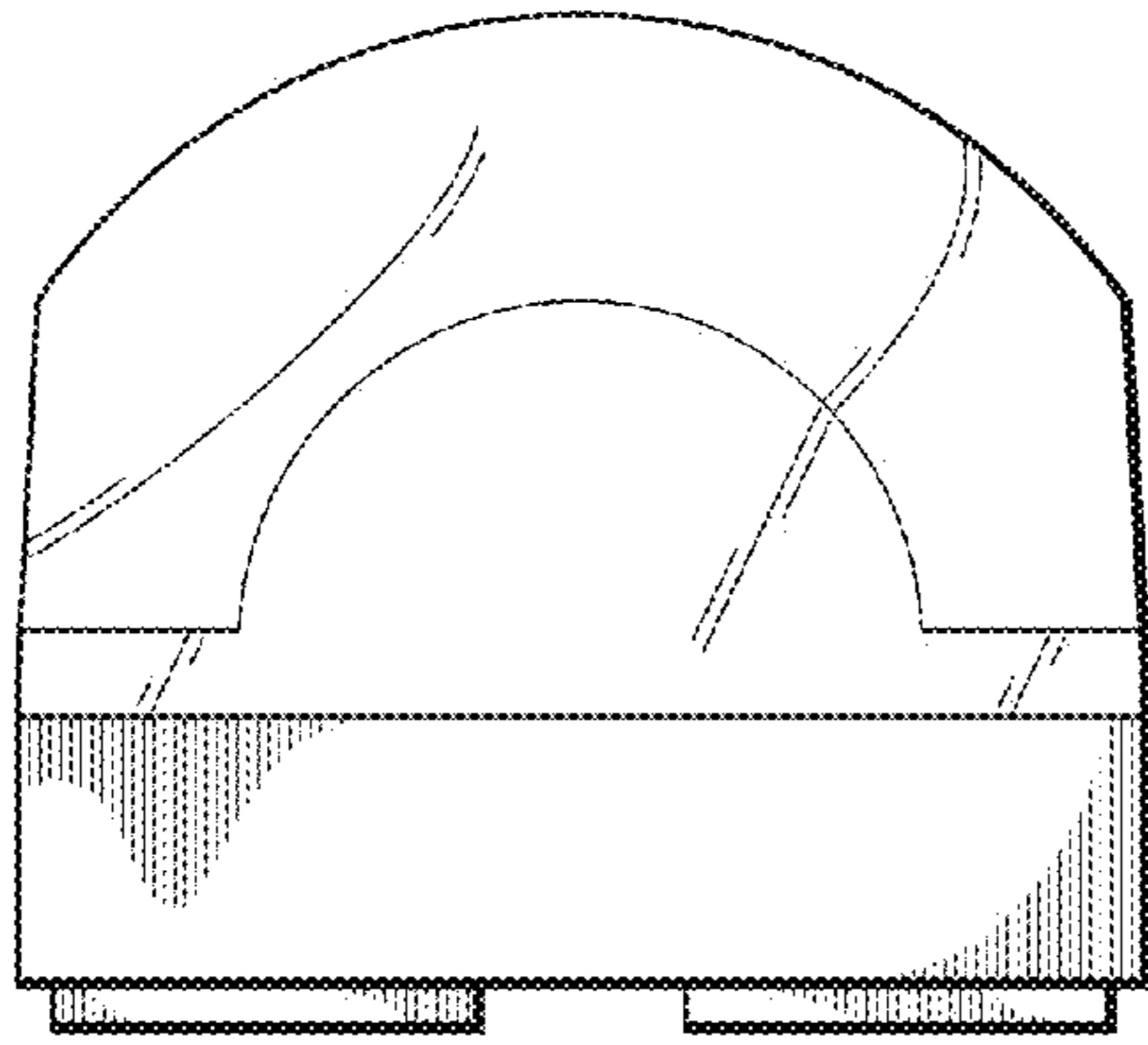


FIG. 39

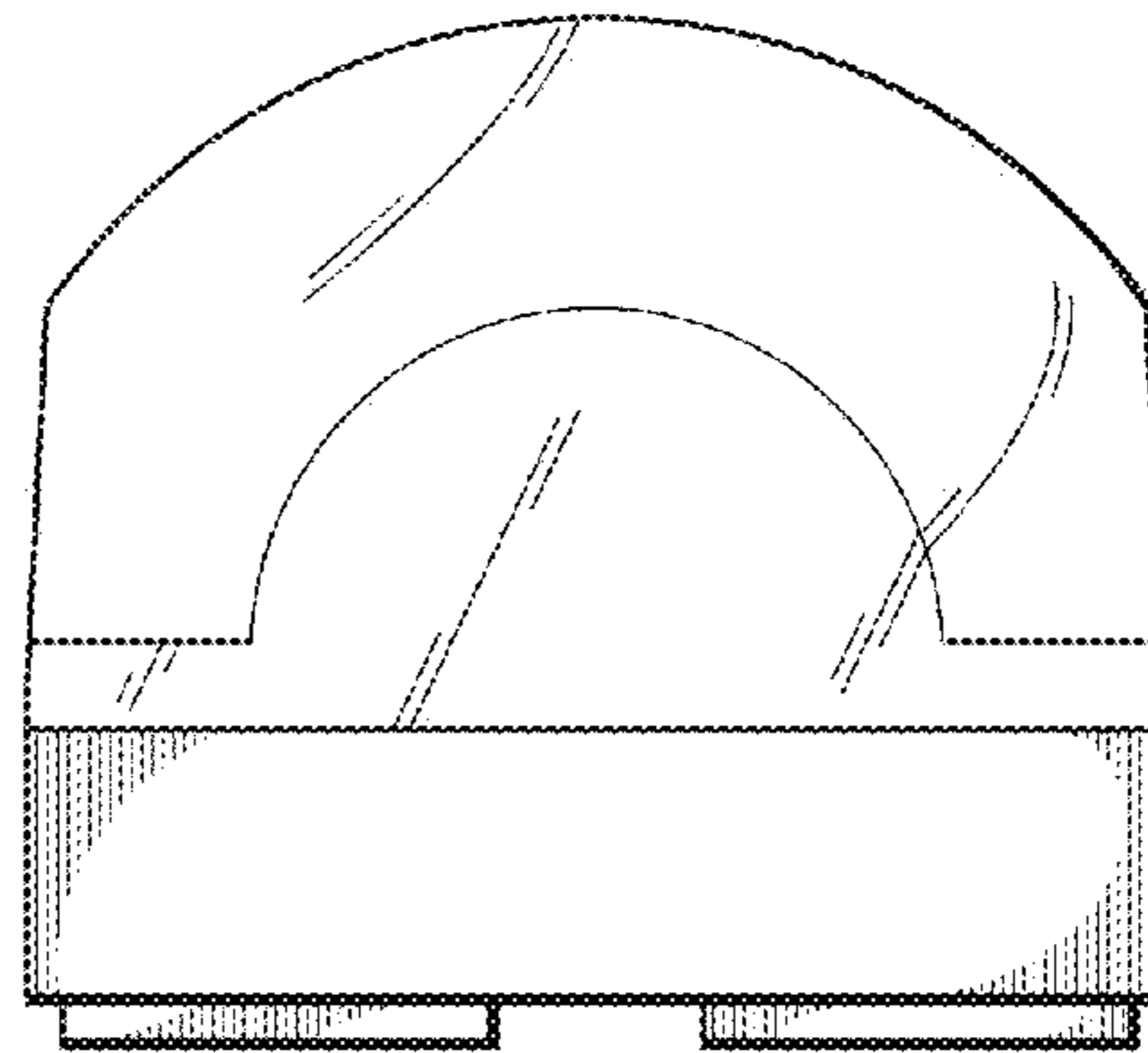


FIG. 40

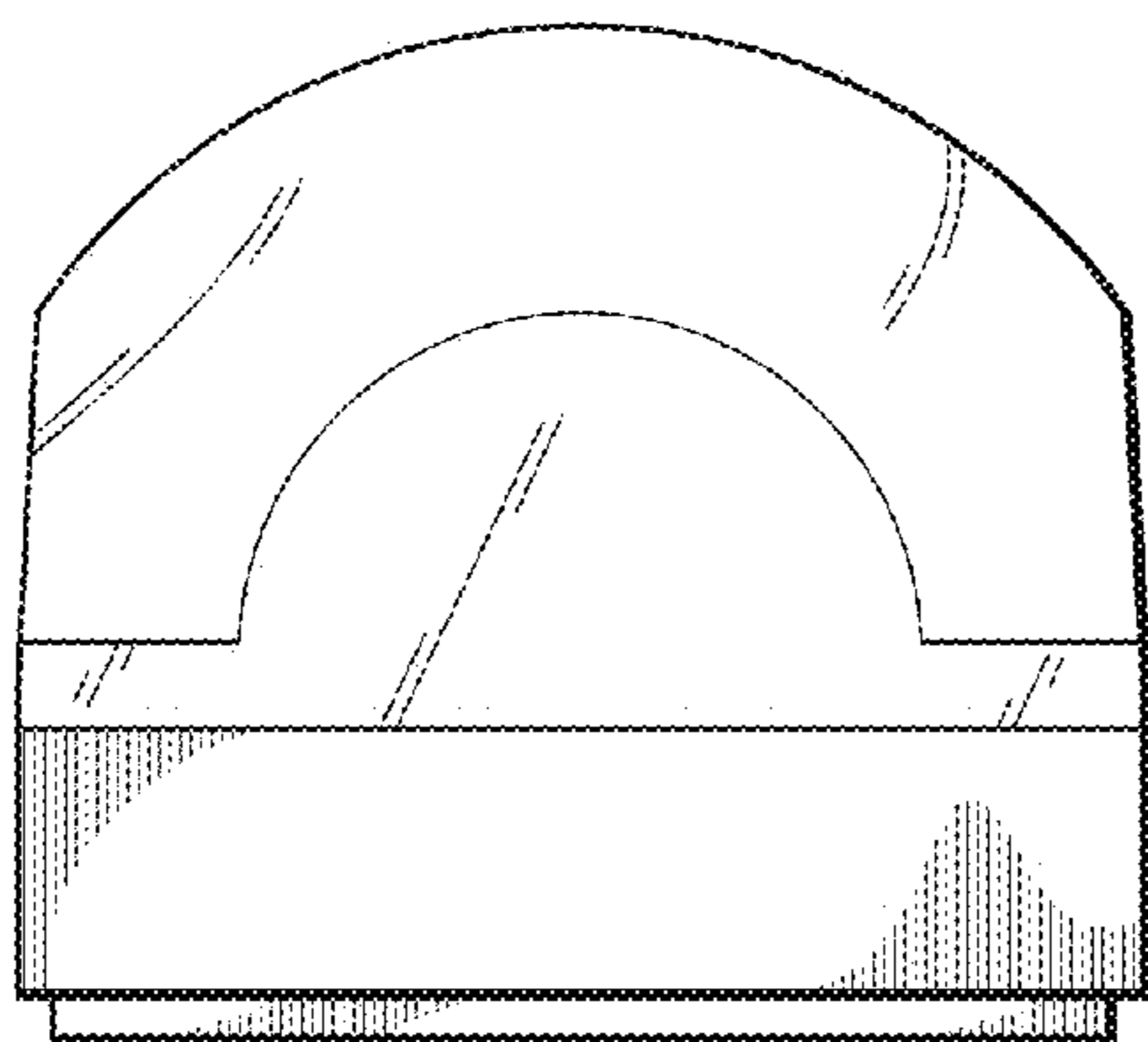


FIG. 41

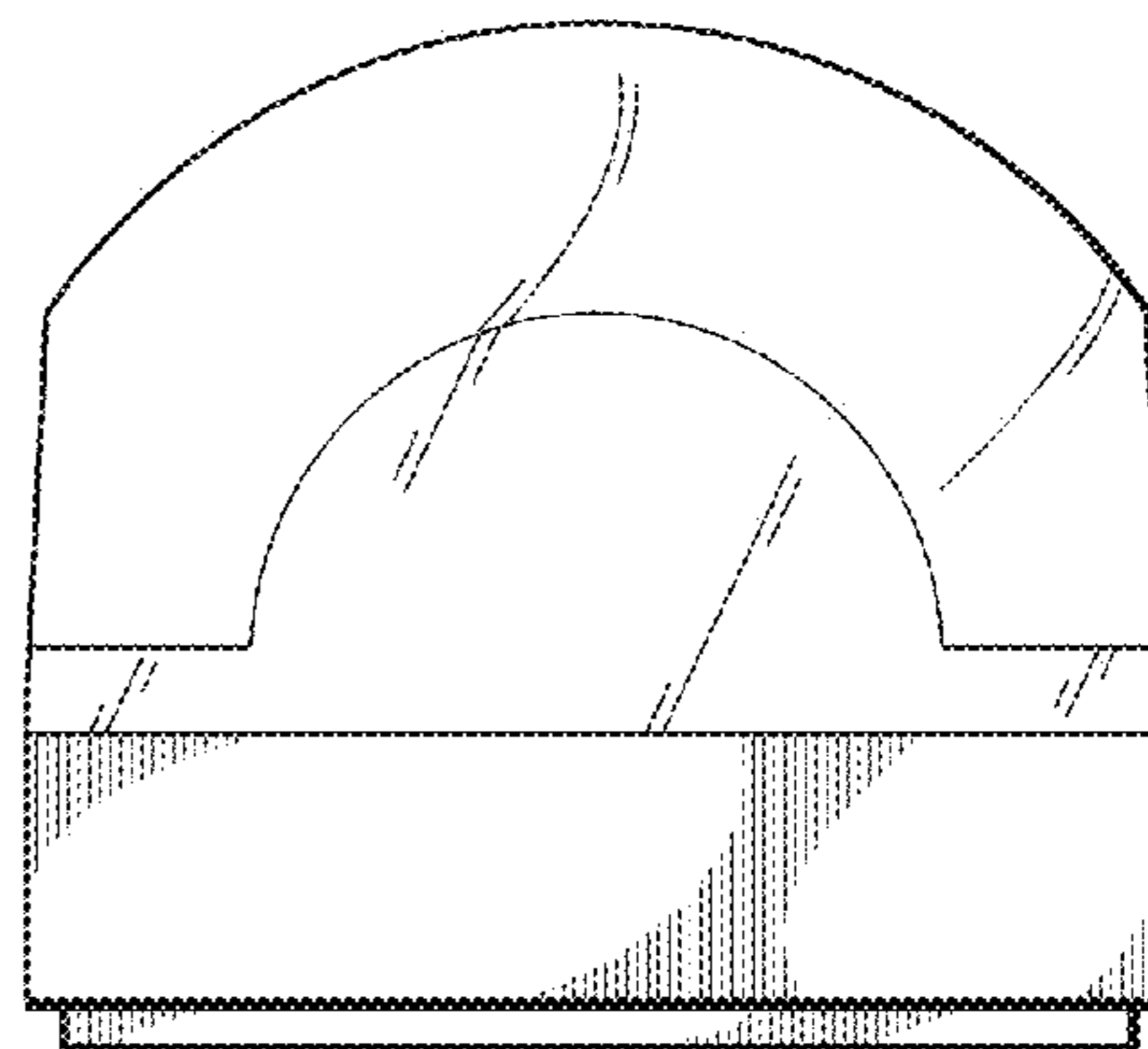


FIG. 42